ScioSense

LTDC-X3

2-Channel LiDAR Time-to-Digital Converter

LTDC-X3 datasheet

Revision: 4

Release Date: 2026-08-20

Document Status: Production

LTDC-X3 is a high-performance 2-channel time-to-digital converter specifically designed for single-beam LIDAR systems. It has a separate START channel, two STOP channels, measures up to 8 pulses on rising and/or falling edges, has a pulse-pair resolution as low as 5 ns, a typical rms resolution of 20 ps and a range up to 16 µs. It integrates a start pulse generator for generation of trigger signals to an external laser diode driver.

Equipped with a quad SPI interface, the data rate can be as high as 50MHz / 200MBPS.

It comes in a 4x4 QFN32 package and works in the industrial temperature range.

Key Benefits

- Simple data post-processing thanks to calibrated results
- Optimized for LiDAR applications
- High efficiency thanks high sample rate
- Compact design thanks to small package and low number of external components
- Reduced cooling thanks to low power consumption

Key Features

- Two TDC stop channels, one separate TDC start channel
- Pulse measurements on rising and falling edge
- Minimum pulse width 2 ns
- Minimum pulse-to-pulse spacing 3 ns (combined channels)
- Stop measurement of up to 8 pulses on rising and falling edge
- Stop mask window
- Maximum measuring range 16 µs
- Typical rms resolution 30 ps, 20 ps with HighRes = 4
- Stop input comparator compatible with LVDS
- 50MHz/200MBPS Quad SPI interface
- Start pulse generator including configurable phase noise

Applications

- Robotics LiDAR
- Range finders
- Door scanners
- Safety scanners

Properties

- Supply voltage 3.3 V
- Temperature range -40°C to +105°C
- QFN32 package

Content Guide

Content Guide **3**

1 Block Diagram **4**

2 Pin Assignment **5**

3 Absolute Maximum Ratings **7**

4 Recommended Operating Conditions **8**

5 Typical Characteristics **10**
5.1 Converter Characteristics 10
5.2 SPI Timings 11

6 Register Description **12**
6.1 Register Overview 12
6.2 Detailed Register Description 13

7 Detailed Description **26**
7.1 Input Structure for Time Measurement 27
7.2 Start-up Sequence 30
7.3 Time Measurements and Results 30
7.4 Trigger Generation Module 34
7.5 QSPI Communication Interface 36
7.6 QSPI Read Access during TDC Measurement 46

8 Application Information **50**
8.1 Schematic 50

9 Soldering information **51**

10 Package drawings & markings **52**

11 Ordering information **54**

12 RoHS Compliance & ScioSense Green Statement **55**

13 Copyrights & Disclaimer **55**

14 Document status **56**

15 Revision information **56**

1 Block Diagram

The functional blocks of this device are shown below.

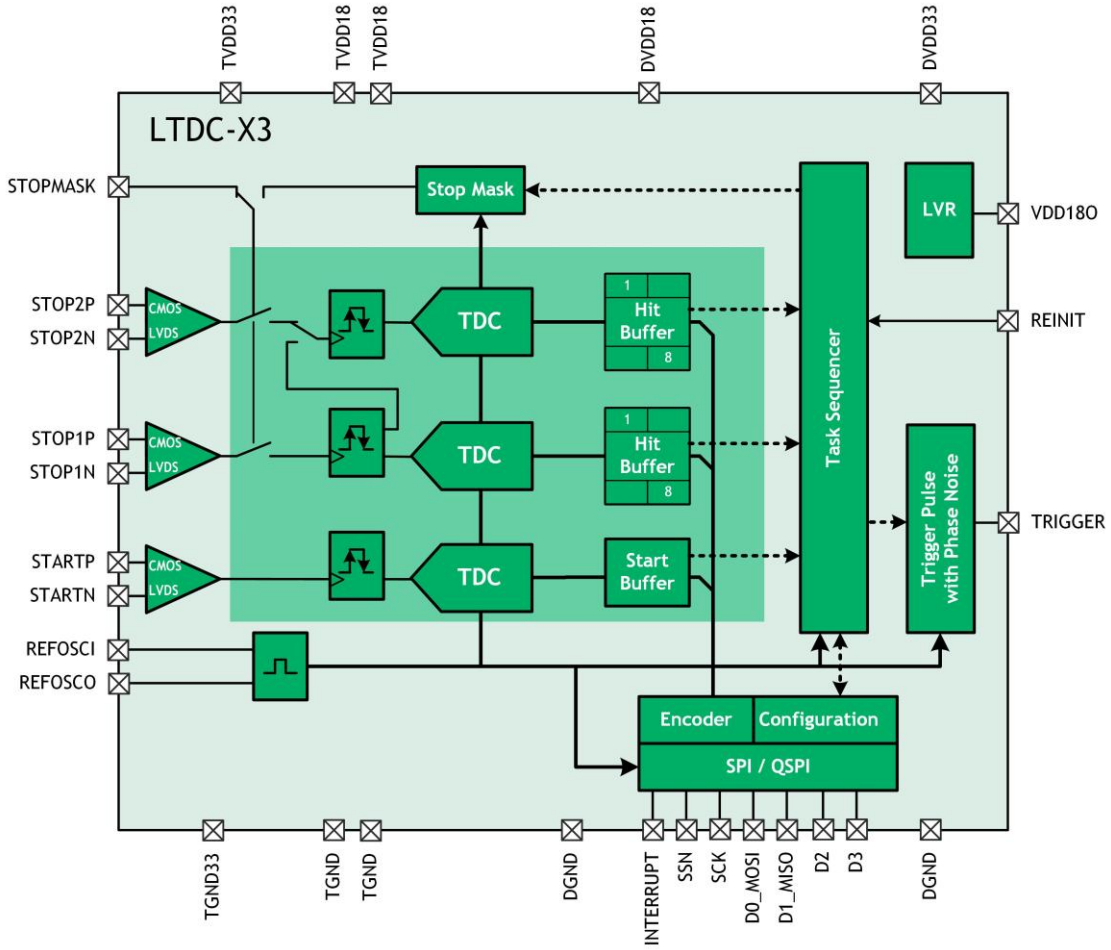


Figure 1: Functional Blocks

2 Pin Assignment

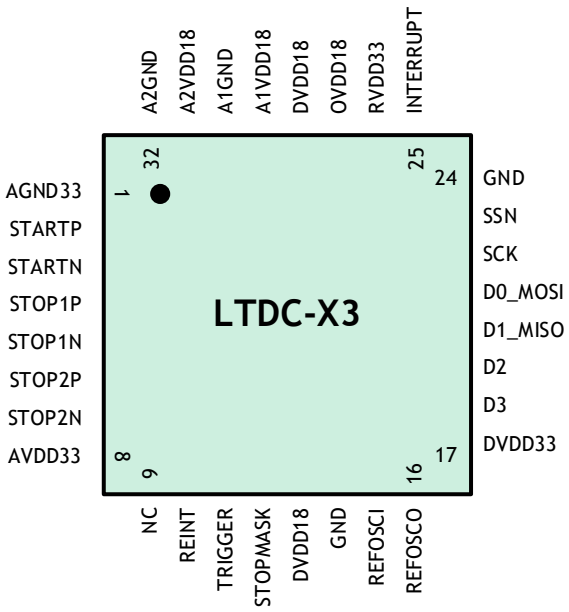


Figure 2: Pin diagram

Table 1: Pin description

Pins	Pin Name	Pin Type[1]	Description	If not used
1	AGND33	S	Ground supply for time front-end	
2	STARTP	LVDSP_DI	Positive LVDS / CMOS start input	
3	STARTN	LVDSN	Negative LVDS start input	
4	STOP1P	LVDSP_DI	Positive LVDS / CMOS input for stop channel 1	
5	STOP1N	LVDSN	Negative LVDS input for stop channel 1	
6	STOP2P	LVDSP_DI	Positive LVDS / CMOS input for stop channel 2	
7	STOP2N	LVDSN	Negative LVDS input for stop channel 2	
8	AVDD33	S	3.3V positive supply for time front-end	
9	NC	IO	Not connected	GND
10	REINIT	DI_PD	Re-init TDC command	
11	TRIGGER	DO	Trigger pulses with phase noise	
12	STOPMASK	DI_PD	Input signal to mask the stop inputs	
13	DVDD18	S	1.8V supply for digital and IO units	

[1] S supply pad, AIO analog I/O, DI digital input, LVDSP_DI LVDS positive input / CMOS digital input, LVDSNLVDS negative input, DI_PU digital input with pull-up, DI_PD digital input with pull-down, DI_PU_STdigital Schmitt trigger input with pull-up, DI_PD_ST digital Schmitt trigger input with pull-down, DIO_PU I/O with pull-up, DIO_PD digital I/O with pull-down, DIO_T digital I/O / tristate, DO digital output, DO_PD digital output with pull-down, DO_ODPU digital output open drain with pull-up, DO_ODPD digital output open drain with pull-down

14	GND	S	Ground for digital blocks and IO units	
15	REFOSCI	AIO	Input for quartz as reference clock	
16	REFOSCO	AIO	Output for quartz as reference clock	
17	DVDD33	S	3.3V supply for digital and IO units	
18	D3	DIO_T	QSPI/SPI Data Output 3	
19	D2	DIO_T	QSPI/SPI Data Output 2	
20	D1	DIO_T	QSPI/SPI Data Output 1 / Master Input Slave Output	
21	D0	DIO_T	QSPI/SPI Data Output 0 / Master Output Slave Input	
22	SCK	DI	QSPI/SPI clock	
23	SSN	DI_PU	QSPI/SPI chip select	
24	GND	S	Ground for digital blocks and IO units	
25	INTERRUPT	DO	Interrupt output	
26	RVDD33	S	3.3V positive supply for LDO	
27	OVDD18	S	1.8V supply for digital and IO units, regulator output	
28	DVDD18	S	1.8V supply for digital and IO units	
29	A1VDD18	S	1.8V supply for analog block	
30	GND1	S	Ground for analog 1.8V block	
31	A2VDD18	S	1.8V supply for analog block	
32	A2GND18	S	Ground for analog 1.8V block	

3 Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated under "Operating Conditions" is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2: Absolute Maximum Ratings

Symbol	Parameter	Min	Max	Units	Comments
Electrical Parameters					
VDD33	3.3V Supply Voltage to Ground	-0.3	4.0	V	
VDD18	1.8V Supply Voltage to Ground	-0.3	2.3	V	
V_{DLVDS}	DC Voltage at LVDS START and STOP pins	-0.3	VDD33+0.3	V	
V_{DIO}	DC Voltage at D0, D1, D2, D3, SSN, SCK, INTERRUPT, STOPMASK and TRIGGER pins	-0.3	VDD33+0.3	V	
I_{SCR}	Input current (latch-up immunity)	-100	100	mA	JESD78E
P_{tot}	Total Power Dissipation		150	mW	
Electrostatic Discharge					
ESD_{HBM}	Electrostatic Discharge HBM	± 1000		V	JS-001-2017
ESD_{CDM}	Electrostatic Discharge CDM	± 500		V	JS-002-2018
Temperature Ranges and Storage Conditions					
T_J	Operating Junction Temperature	-40	125	°C	
T_{STRG}	Storage Temperature Range	- 65	150	°C	
T_{BODY}	Package Body Temperature		260	°C	IPC/JEDEC J-STD-020 [2]
RH_{NC}	Relative Humidity (non-condensing)	5	85	%	
MSL	Moisture Sensitivity Level	3			Maximum floor life time of 168h

[2] The reflow peak soldering temperature (body temperature) is specified according to IPC/JEDEC J-STD-020 "Moisture/Reflow Sensitivity Classification for Non-hermetic Solid State Surface Mount Devices." The lead finish for Pb free leaded packages is "Matte Tin" (100 % Sn)

4 Recommended Operating Conditions

Recommended operating ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Test conditions for guaranteed specification are expressly denoted.

Table 3: Recommended operation conditions

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Power Supply						
VDD33	DC supply voltage VDD33		3.0	3.3	3.6	V
VDD18	DC voltage at VDD18 pin	Supplied from chip	1.62	1.8	1.98	V
t_{POR}	Startup time			10		ms
Temperature						
T_A	Operating free air temperature [3]		-25	25	105	°C
LVDS Input						
V_{ID}	LVDS differential input voltage		100			mV
V_{ICM}	LVDC common mode input voltage		$V_{ID}/2$	1.25	2.4 – $V_{ID}/2$	mV
t_{pmin_LVDS}	Minimum pulse width			2	3	ns
Digital Inputs and Outputs						
$V_{IL,CMOS}$	CMOS input low voltage				0.4	V
$V_{IH,CMOS}$	CMOS input high voltage		VDD33 – 0.4			
$t_{p,minCMOS}$	Pulse width for detection			3	4	ns
I_{leak}	Input leakage current		-10		10	µA
C_{in}	Input capacitance				10	pF
V_{OH}	High level output voltage	I_{out} = 24 mA	0.8 * VDD33			V
V_{OL}	Low level output voltage	I_{out} = 24 mA			0.4	V
I_{LEAKTS}	Tri-state output leakage current	V_{out} = VDD33	-10		10	µA
V_{ID}	Minimum differential input voltage		100			mV
V_{hys}	Hysteresis	LVDS CMOS	40 0.2*AVDD33			mV
V_{ICM}	Common input voltage	GND2 =A2GND18	VID/2	1.25	2.4-VID/2	V

[3] Recommended Operating Ratings indicate conditions for which the device is functional, but do not guarantee specific performance limits. Test conditions for guaranteed specification are explicitly denoted.

Oscillator						
F_{OSC}	Oscillator Frequency		4	10	12.5	MHz
DC	Duty cycle		40		60	%
I_{CC}	Current on V_{CC}	After initial startup			0.9	mA
I_{DD}	Current on V_{DD}				0.1	mA
T_{STUP}	Startup time	Settling at target frequency ±0.01%			10	ms
R_{START}	Internal feedback resistance			1		MΩ
Current Consumption						
	Standby current				100	µA
	Current after INIT	No hits				mA
	Measurement current	100 ksps			50 [4]	mA

[4] Simulated, to be confirmed.

5 Typical Characteristics

The following test levels apply to all following characteristics.

Table 4: Test levels

Test Level	Description
I	100% production tested.
II	100% production tested at 25°C and guaranteed by design and characterization testing
III	Parameter is guaranteed by design and characterization testing
IV	Sample tested
V	Parameter is a typical value only.

5.1 Converter Characteristics

General Conditions: VDD33 = 3.3 V; VDD18 = 1.8 V; T_A = 0 °C to 80 °C.

Table 5: Characteristics

Symbol	Description	Conditions	TL	Min	Typ	Max	Unit
Accuracy of Time Measurements							
RMS	Single-shot RMS resolution	-25 to +85° C High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x)	IV		 30 25 20	 45 37 30	ps
INL	Integral non-linearity		IV			20	ps
DNL	Differential non-linearity		V		5		ps
	No missing code	At time quantization level	III		Assured		
	Channel to channel isolation	At same times measured	IV		100	200	ps
	Offset between START and STOP1		IV		500	1000	ps
	Offset drift between START and STOP1				t.b.d.		ps/K
	Offset error between STOP1 and STOP2	High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x)	V		100 150 200		ps
	Offset drift between STOP1 and STOP2 over temperature	High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x)	IV		0.5 1 1.5	3	ps/K
P2P	Pulse-to-pulse spacing	High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x) Channel_Chain = on			15 30 45 3		ns

Switching Performance							
t_{CONV}	Converter latency (INT set)	High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x)	III		t.b.d.		ns
	Peak conversion rate	High_Resolution = 0 (off) High_Resolution = 1 (2x) High_Resolution = 2 (4x)	III			50 20 10	Msps
	Maximum read-out rate	SCK = 50MHz Opcode + 48-Bit Opcode + 16-Bit	III	 0.9		 2.1	Msps

5.2 SPI Timings

SPI slave timing values are described in the following table (the measurement points are done at 0.2·VDD and 0.8·VDD):

Table 6: SPI characteristics

Symbol	Parameter	Min	Max	Units
f_{sck}	Serial clock frequency		50	MHz
$t_{pwh,sck}$	Serial clock pulse width HI state	10-5%		ns
$t_{pwl,sck}$	Serial clock pulse width LO state	10-5%		ns
$t_{pwh,ssn}$	SSN pulse width between write cycles	20		ns
$t_{su,ssn}$	SSN setup time before SCK rising	3		ns
$t_{hd,ssn}$	SSN hold time after SCK rising	3		ns
$t_{su,mosi}$	Data setup time prior to clock edge	2		ns
$t_{hd,mosi}$	Data hold time after clock edge	2		ns
$t_{dv,mosi}$	Data valid after falling clock edge		8	ns
$t_{zx,miso}$	HighZ to output time		8	ns
$t_{xz,miso}$	Output to HighZ time		8	ns

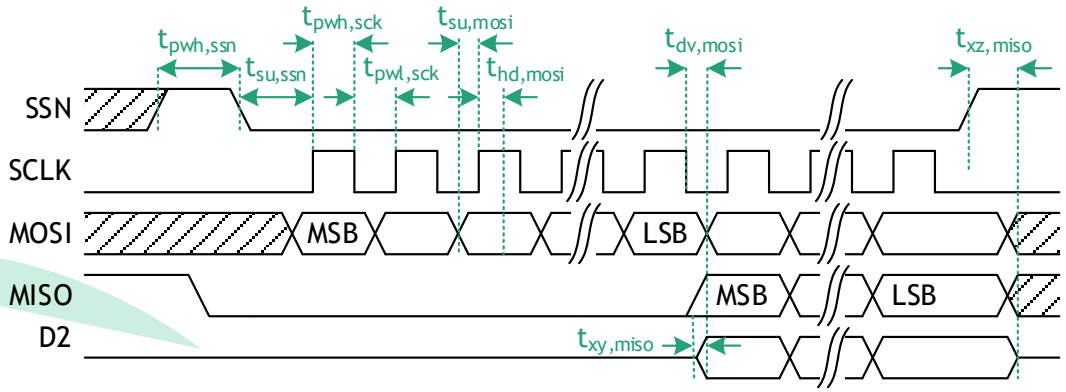


Figure 3: SPI Timings

6 Register Description

This section describes the registers of the LTDC-X3, which enable the host system to

- Configure the LTDC-X3 and set the operating mode
- Read back the timing information
- Read back STATUS information

6.1 Register Overview

Table 7: Register Overview

Address	Name	Access	Description
0x00 to 0x0F	**CFG0 TO CFG15**	RW	TDC configuration registers
0x11	**WRN_LOCK**	RW	QSPI configuration registers
0x12	**ENC_SET**	RW	
0x13	**COM_SET**	RW	
0x14	**CH_CFG20**	RW	
0x15 to 0x17	**TOF_CH1**	RO	Result registers: Time of flight channel 1 Pulse width channel 1 Time of flight channel 2 Pulse width channel
0x18 to 0x1A	**PW_CH1**	RO	
0x1B to 0x1D	**TOF_CH2**	RO	
0x1E to 0x20	**PW_CH2**	RO	
0x21	**DEV_STATE**	RO	Reserved
0x22	**TDC_STAT_REG1**	RO	TDC status
0x23	**TDC_STAT_REG2**	RO	
0x24	**TDC_STAT_REG3**	RO	
0x25	**TDC_STAT_REG4**	RO	
0x26 to 0x28	**N.C.**	RO	
0x2A to 0x2F	**ANALOG_CFGX**	RW	Analog configuration
0x30 to 0x33	**CALIB_CFGX**	RW	Delay line calibration
0x3A	**TRIG_ID**	RW	Trigger configuration
0x3B	**TRIG_NOISE**	RW	
0x3C	**TRIG_PERIOD**	RW	
0x40 to 0x46	**N.C.**	-	Not used

Note: register addresses that are not listed here are not used and set by default to 0.

6.2 Detailed Register Description

6.2.1 CFG0 (Address 0x00)

Table 8: Register CFG0

Address 0x00		CFG0		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7				reserved
6	**SSN_INIT_ENA**	0x00	RW	Selects source of re-initialization of the TDC: 0: SINGLE ACCESS, restart by opcode TDC_REINIT or pin REINIT 1: DMA AUTOMATIC ACCESS, SSN constantly at 0 during read-out, TDC is restarted automatically when SSN is high again
5:4	**HIGHRES**	0x00	RW	Settings for higher resolution 0: normal resolution 1: medium 2: high resolution
3	**CHANNEL_COMBINE**	0x00	RW	0: Stop1 measured on one channel only 1: Stop1 measured on both stop channels alternately for halving pulse-to-pulse distance
2				Set 1. reserved
1	**HIT_ENA_STOP2**	0x00	RW	Software enable of Stop2 input
0	**HIT_ENA_STOP1**	0x00	RW	Software enable of Stop1 input

6.2.2 CFG1 (Address 0x01)

Table 9: Register CFG1

Address 0x01		CFG1		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:6				reserved
5:3	**HITBUFSIZE2**	0x00	RW	Hit buffer size 0: 8 hits 1: 1 hit 2: 2 hits ... 8: 8 hits
2:0	**HITBUFSIZE1**	0x00	RW	

6.2.3 CFG2 (Address 0x02)

Table 10: Register CFG2

Address 0x02		CFG2		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TIMEOUT**	0x00	RW	8-bit timeout counter which is synchronized to the start pulse (100 ns uncertainty) and used for timeout of TDC, ToF and conversion. 0: timeout generation off 1: period of the reference clock 2: periods of the reference clock … 255: periods of the reference clock

6.2.4 CFG3 (Address 0x03)

Table 11: Register CFG3

Address 0x03		CFG3		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**DELSTM_DLY [7:0]**	0x00	RW	Delay for STOP mask. Counted in **DELTRIG_LSB**

6.2.5 CFG4 (Address 0x04)

Table 12: Register CFG4

Address 0x04		CFG4		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:4				reserved
3:0	**DELSTM_DLY [11:8]**	0x00	RW	Delay for STOP mask. Counted in **DELTRIG_LSB**

CFG5 to CFG7 (Address 0x05 to 0x07)

Table 13: Registers CFG5 to CFG7

Address 0x03		CFG5		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**REFCLKDIV [7:0]**	0x00	RW	Low word. Defines the LSB at the output interface as fraction of the reference clock period
Address 0x06		**CFG6**		
7:0	**REFCLKDIV [15:8]**	0x00	RW	Mid word. Defines the LSB at the output interface as fraction of the reference clock period
Address 0x07		**CFG7**		
7:0	**REFCLKDIV [23:16]**	0x00	RW	HIGH WORD. Defines the LSB at the output interface as fraction of the reference clock period

6.2.6 CFG8 (Address 0x08)

Table 14: Register CFG8

Address 0x08		CFG8		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:6	**NOT USED**	0x00	RW	Not used
5	**STOP_MASK_ENA**	0x00	RW	Enables noise mask which is based on the sourse selected under **STOP_MASK_EXT**. The length of the mask is defined under **DELSTM_DLY** 0: stops enabled 1: stops masked
4	**STOP_MASK_EXT**	0x00	RW	Selects source of noise mask 0: by noise mask delay line 1: by noise mask pin
3:2	**DELSTM_LSB**	0x00	RW	Length of LSB of stop mask as a fraction of the reference clock period: 0: 1/1024 * T_{ref} (e.g.0.097 ns @ 10 MHz) 1: 2/1024 * T_{ref} (e.g.0.195 ns @ 10 MHz) 2: 5/1024 * T_{ref} (e.g.0.488 ns @ 10 MHz) 3: 10/1024 * T_{ref} (e.g..0.976 ns @ 10 MHz)
1:0	**DELTRIG_LSB**	0x00	RW	Length of LSB of trigger delay as a fraction of the reference clock period. Same setting as DELSTM_LSB

6.2.7 CFG9 (Address 0x09)

Table 15: Register CFG9

Address 0x09		CFG9		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TRIG_MAX_DEL**	0x00	RW	Maximum delay count for tigger output in units of DELTRIG_LSB

6.2.8 CFG10 to14 (Address 0x0A to 0x0D)

Address 0x0A: 63 or 0x3F

Address 0x0B: 224 or E0

Address 0x0C: 101 or 0x65

Address 0x0D: 222 or 0xDE

Address 0x0E: 227 or 0xE3

6.2.9 CFG15 (Address 0x0F)

Table 16: Register CFGF3

Address 0x0F		CFG15		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**NOT USED**			Reserved, set 0x27

6.2.10 WRN_LOCK (Address 0x11)

Table 17: Register WRN_LOCK

Address 0x11		WRN_LOCK		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
0	**WRN_LOCK**	0x1	RW	Write lock/unlock register 0: Functional registers are not writable 1: Functional registers are writable

6.2.11 COM_SET (Address 0x13)

Table 18: Register COM_SET

Address 0x13		COM_SET		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:4	**DUMMY_CYCLE**	0x0	RW	Sets the number of dummy cycles inserted in the Dual SPI and Quad SPI communication. Values can range from 0 to up to 15 clock cycles 1 is typically recommended..
3:2	**TR_MODE**	0x0	RW	Transfer mode for reading from hit buffer: 0: Default mode. The master reads three bytes of TOF and three bytes of PWSTOP 1:In this mode, the least significant bytes of TOF and PWSTOP are discarded, this leads to an increase in transmission speed at the expense of measurement accuracy. 2: In this mode, only the TOF is read and the PWSTOP is discarded. It is the fastest reading mode.
1	**EN_DUAL**	0x0	RW	1: Enables dual mode for the QSPI interface
0	**EN_QUAD**	0x0	RW	1: Enables quad mode for the QSPI interface

6.2.12 CH_CFG20 (Address 0x14)

Table 19: Register CH_CFG20

Address 0x14		CH_CFG20		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7	**MASK_OV**	0x1	RW	Overflow time (0xFFFFFE) in TOF will also mask PW with 0xFFFE
6:3	**BUFF_SIZE**	0xf	RW	Set to 15
2:1	**CH_CFG**	0x3	RW	Channel read out configuration 0: OFF 1: read channel 1 only 2: read channel 2 only 3: read channel 1 & 2 alternatingly
0	**ACCMODE**	0x1	RW	Defines the access mode. 0: Single access. only one TOF and PWSTOP. Value is read at a time 1: Incremental access. In this mode, the QSPI slave refreshes the TDC data every time it has completed the reading of the previous one.

6.2.13 TOF_CH1_H (Address 0x15)

Table 20: Register TOF_CH1_H

Address 0x15		TOF_CH1_H		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_CH1 [23:16]**	0x00	RO	TDC channel 1 time-of-flight data [23:16]

6.2.14 TOF_CH1_M (Address 0x16)

Table 21: Register TOF_CH1_M

Address 0x16		TOF_CH1_M		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_CH1 [15:8]**	0x00	RO	TDC channel 1 time-of-flight data [15:8]

6.2.15 TOF_CH1_L (Address 0x17)

Table 22: Register TOF_CH1_L

Address 0x17		TOF_CH1_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_CH1 [7:0]**	0x00	RO	TDC channel 1 time-of-flight data [7:0]

6.2.16 PW_CH1_H (Address 0x18)

Table 23: Register PW_CH1_H

Address 0x18		PW_CH1_H		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH1 [23:16]**	0x00	RO	TDC channel 1 pulse width data [23:16]

6.2.17 PW_CH1_M (Address 0x19)

*Table 24: Register **PW_CH1_M***

Address 0x19		PW_CH1_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH1 [15:8]**	0x00	RO	TDC channel 1 pulse width data [15:8]

6.2.18 PW_CH1_L (Address 0x1A)

Table 25: Register PW_CH1_L

Address 0x1A		PW_CH1_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH1 [7:0]**	0x00	RO	TDC channel 1 pulse width data [7:0]

6.2.19 TOF_CH2_H (Address 0x1B)

Table 26: Register TOF_CH2_H

Address 0x1B		TOF_CH2_H		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_CH2 [23:16]**	0x00	RO	TDC channel 2 time-of-flight data [23:16]

6.2.20 TOF_CH2_M (Address 0x1C)

Table 27: Register TOF_CH2_M

Address 0x1C		TOF_CH2_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_CH2 [15:8]**	0x00	RO	TDC channel 2 time-of-flight data [15:8]

6.2.21 TOF_CH2_L (Address 0x1D)

Table 28: Register TOF_CH2_L

Address 0x1D		TOF_CH2_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TOF_C2 [7:0]**	0x00	RO	TDC channel 2 time-of-flight data [7:0]

6.2.22 PW_CH2_H (Address 0x1E)

Table 29: Register PW_CH2_H

Address 0x1E		PW_CH2_H		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH2 [23:16]**	0x00	RO	TDC channel 2 pulse width data [23:16]

6.2.23 PW_CH2_M (Address 0x1F)

*Table 30: Register **PW**_CH2_M*

Address 0x1F		PW_CH2_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH2 [15:8]**	0x00	RO	TDC channel 2 pulse width data [15:8]

6.2.24 PW_CH2_L (Address 0x20)

Table 31: Register PW_CH2_L

Address 0x20		PW_CH2_L		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**PW_CH2 [7:0]**	0x00	RO	TDC channel 2 pulse width data [7:0]

6.2.25 DEV_STATE (Address 0x21)

Table 32: Register DEV_STATE

Address 0x21		DEV_STATE		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
1:0	**DEV_STATE**	0x00	RO	Device status bits b01: Power-on reset was released b10: Configuration registers were written b11: Chip was initialized

6.2.26 TDC_STAT_REG1 (Address 0x22)

Table 33: Register TDC_STAT_REG1

Address 0x22		TDC_STAT_REG1		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
5	**EF_STO2_R**	0x00	RO	Stop rise 2 FIFO flag empty
4	**FF_STO2_R**	0x00	RO	Stop rise 2 FIFO flag full
3	**EF_STO1_R**	0x00	RO	Stop rise 1 FIFO flag empty
2	**FF_STO1_R**	0x00	RO	Stop rise 1 FIFO flag full
1	**EF_STA_R**	0x00	RO	Start FIFO flag empty
0	**NOT USED**			

6.2.27 TDC_STAT_REG2 (Address 0x23)

Table 34: Register TDC_STAT_REG2

Address 0x23		TDC_STAT_REG2		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
3	**EF_STO2_F**	0x00	RO	Stop fall 2 FIFO flag empty
2	**FF_STO2_F**	0x00	RO	Stop fall 2 FIFO flag full
1	**EF_STO1_F**	0x00	RO	Stop fall 1 FIFO flag empty
0	**FF_STO1_F**	0x00	RO	Stop fall 1 FIFO flag full

6.2.28 TDC_STAT_REG3 (Address 0x24)

Table 35: Register TDC_STAT_REG3

Address 0x24		TDC_STAT_REG3		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
6:4	**HITCNT_CH2R**	0x00	RO	Number of hits for rising edge in hit buffer 2
2:0	**HITCNT_CH1R**	0x00	RO	Number of hits for rising edge in hit buffer 1

6.2.29 TDC_STAT_REG4 (Address 0x25)

Table 36: Register TDC_STAT_REG4

Address 0x25		TDC_STAT_REG4		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
6:4	**HITCNT_CH2F**	0x00	RO	Number of hits for falling edge in hit buffer 2
2:0	**HITCNT_CH1F**	0x00	RO	Number of hits for falling edge in hit buffer 1

6.2.30 ANALOG_CFG0 (Address 0x2A)

Table 37: Register ANALOG_CFG0

Address 0x2A		ANALOG_CFG0		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**DEFAULT**	0xC0	RW	Use default

6.2.31 ANALOG_CFG1 (Address 0x2B)

Table 38: Register ANALOG_CFG1

Address 0x2B		ANALOG_CFG1		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**DEFAULT**	0x04F	RW	Use default

6.2.32 ANALOG_CFG2 (Address 0x2C)

Table 39: Register ANALOG_CFG2

Address 0x2A		ANALOG_CFG2		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**DEFAULT**	0x16	RW	Use default

6.2.33 ANALOG_CFG3 (Address 0x2D)

Table 40: Register ANALOG_CFG3

Address 0x2D		ANALOG_CFG3		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**DEFAULT**	0x42	RW	Use default

6.2.34 ANALOG_CFG4 (Address 0x2E)

Table 41: Register ANALOG_CFG4

Address 0x2E		ANALOG_CFG4		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**NOT_USED**	0x00	RW	Not used

6.2.35 ANALOG_CFG5 (Address 0x2F)

Table 42: Register ANALOG_CFG5

Address 0x2F		ANALOG_CFG5		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7	**CMOS_ENA_STOP2**	0x00	RW	0: Use LVDS levels 1: Enable CMOS threshold for STOP2, STOP1 and START inputs
6	**CMOS_ENA_STOP1**	0x00	RW	
5	**CMOS_ENA_START**	0x00	RW	
4	**LVDS_ENA_STOP2**	0x00	RW	0: Disable LVDS receivers tos save current 1: Enable LVDS receivers for STOP2, STOP and START inputs
3	**LVDS_ENA_STOP1**	0x00	RW	

2	**LVDS_ENA_START**	0x00	RW	
1	**OSC_ENA**	0x00	RW	1: Oscillator enable
0	**IREF_ENA**	0x00	RW	1: Enable reference current source for LVDS, set 1

6.2.36 CALIB_CFGX Addresses 0x30 to 0x33)

Internal calibration registers. Use the following recommended values:
Address 0x30: 0x03
Address 0x31: 0x00
Address 0x32: 0xF0
Address 0x33: 0x00

6.2.37 TRIG_ID (Address 0x3A)

Table 43: Register TRIG_NOISE

Address 0x3B		TRIG_NOISE		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TRIG_ID**	0x00	RW	Defines the seed of pseudo_random_sequence

6.2.38 TRIG_NOISE (Address 0x3B)

Table 44: Register TRIG_NOISE

Address 0x3B		TRIG_NOISE		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
6:5	**TRIG_NOISE**	0x00	RW	Defines the amplitude of the trigger noise
4:1	**TRIG_LENGTH**	0x00	RW	Defines the length of the trigger pulse
0	**TRIG_ON**	0x00	RW	1: enables the trigger

6.2.39 TRIG_PERIOD (Address 0x3C)

Table 45: Register TRIG_PERIOD

Address 0x3C		TRIG_PERIOD		
Bits	**Field Name**	**Default**	**Access**	**Field Description**
7:0	**TRIG_PERIOD**	0x00	RW	8-bit counter which defines the duration of trigger period in multiples of the reference clock period 0: off 1: one trigger pulse every reference clock period … 255: one trigger pulse every 255 reference clock periods

7 Detailed Description

LTDC-X3 is a high-speed, high-resolution TDC designed especially for LiDAR applications. It is based on TDC-GPX2 architecture with a continuously running core, but with a dedicated measurement sequence like a start-stop TDC, starting with the initialization, waiting for hits on the START and STOP inputs, and ending with the interrupt when all hits or a timeout have been detected. It calculates STOP – START time differences and the width of the STOP pulses directly on the chip. LVDS inputs enable an easy integration into fast analog front ends. The QSPI (quad SPI) interface allows high sample rate and data readout via a standard interface.

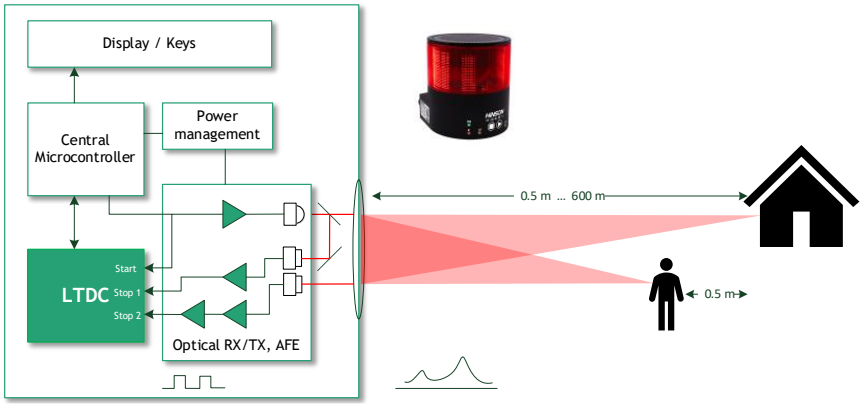


Figure 4: Application diagram

After configuration the chip will be initialized with the receipt of the SPI opcode TDC-INIT. The core is started and the TDC is ready to accept hits. The chip has a START input and two STOP inputs. It calculates the time differences between the STOP channels and the START channel. Time measurements are continuously calibrated against a reference clock which is generated from a 4 to 20 MHz quartz connected to the REFCLK pins. In typical LiDAR designs the START will be triggered by the laser trigger, STOP1 by, the reference beam and STOP2 will be the main measurement channel. On both channels the chip measures rising and falling edge and therefore the time-of-flight and the pulse width for each hit.

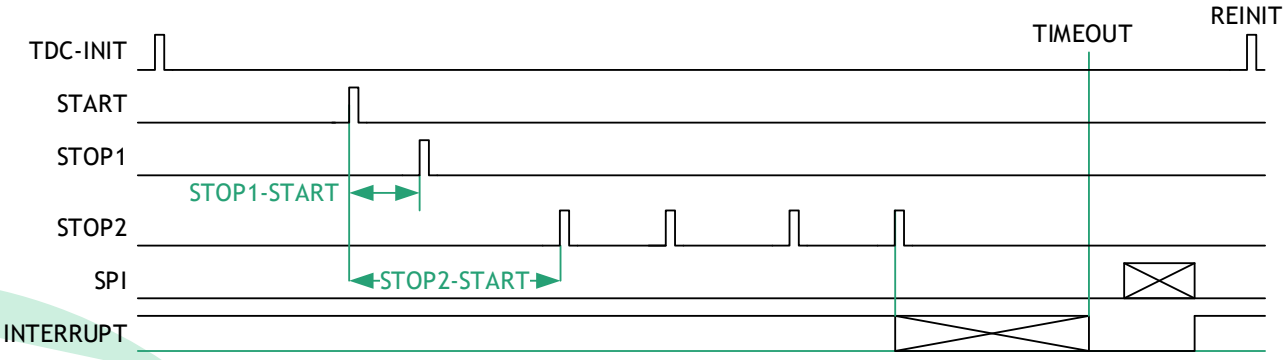


Figure 5: Measurement sequence

The number of expected hits can be configured, and as soon as those are receipt or a timeout occurred an interrupt is set and the external DSP can read the data. The measurement cycle is finished by an automatic or external (SPI or pin) re-initialization which arms the chip for the next measurement.

The reinitialization can be triggered by various sources:

- FIFOs are read: Interrupt and QSPI-SSN are back to high
- Pulse on pin REINIT at any time
- SPI command, resets in addition all internal averaging and calibration units

7.1 Input Structure for Time Measurement

The inputs for START, STOP1 and STOP2 are built with LVDS differential line receivers designed for applications requiring high data rates. They accept differential input signals and translate them to CMOS output levels. The 100Ohm differential input termination is not provided internally, therefore 50Ohm transmission lines and the external termination resistor are needed at pcb level.

The LVDS inputs can be used as single ended receivers to emulate CMOS inputs just connecting the negative input to VDD18 at pcb level. Switching thresholds will be about +/-50 mV around VDD18 without requiring a configuration bit.

The minimum pulse width for the input signals to pass these first comparators is typ. 2 ns for LVDS and 3 ns for CMOS. Shorter pulses might not set the output level high and the hits will be disappear and not trigger the next functional blocks.

7.1.1 START

The base value for START should be zero. The first rising edge on pin START after initialization acts as start time for the TDC measurement and the noise mask window. For operation, the pin has to be enabled. Following configuration bits are relevant:

Table 46: START configuration

Register	Bit	Parameter	Descrition
0x2E **ANALOG_CFG5**	5	**CMOS_ENA_START**	1: enables the CMOS threshold for the START
	2	**LVDS_ENA_START**	1: enables the LVDS START receiver
	0	**IREF_ENA**	1: enables the reference in case of LVDS inputs

7.1.2 STOP1, STOP2

The base value of the stop signal inputs should be zero and the stop pulses high active. The rising and falling edges of the stop signals are measured versus rising edge of the start pulse. The chip has two independent stop channels. With CHANNEL_COMBINE variations of this normal operation mode can be achieved. For operation, the pins have to be enabled. Following configuration bits are relevant:

Table 47: STOP configuration

Register	Bit	Parameter	Descrition

0x2E **ANALOG_CFG5**	7	**CMOS_ENA_STOP2**	1: Enables the CMOS threshold for the STOP2
	6	**CMOS_ENA_STOP1**	1: Enables the CMOS threshold for the STOP1
	4	**LVDS_ENA_STOP2**	1: Enables the LVDS STOP2 receiver
	3	**LVDS_ENA_STOP1**	1: Enables the LVDS STOP1 receiver
	0	**IREF_ENA**	1: Enables the reference in case of LVDS inputs
0x00 **CFG0**	3	**CHANNEL_COMBINE**	1: Stop1 measured on both stop channels alternately for halving pulse-to-pulse distance
	2		Set 1. reserved
	1	**HIT_ENA_STOP2**	1: Software enable of STOP2 input
	0	**HIT_ENA_STOP1**	1: SEoftware enable of STOP1 input

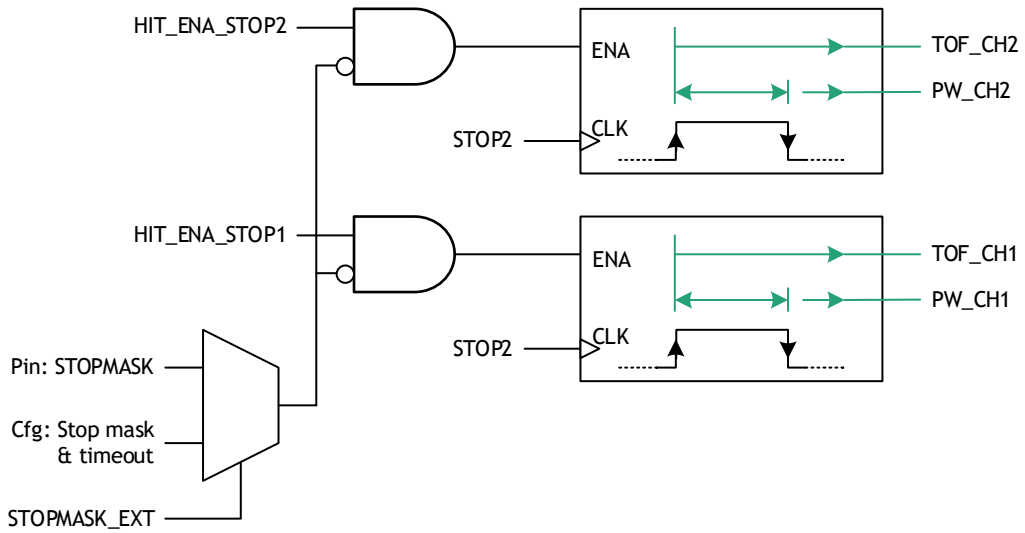


Figure 6: Stop inputs logic

7.1.2.1 Channel Combination for Low Pulse-to-Pulse Spacing

With **CHANNEL_COMBINE = 3** the two stop channels 1 & 2 are connected to one input pin STOP1. The stop pulses at the input pin are distributed alternatingly between the combined channels.

The advantages of combining channels lie in

- Excellent pulse-to-pulse spacing
- Keeping excellent pulse width definition
- Doubled BUFFER depth for stop input pin

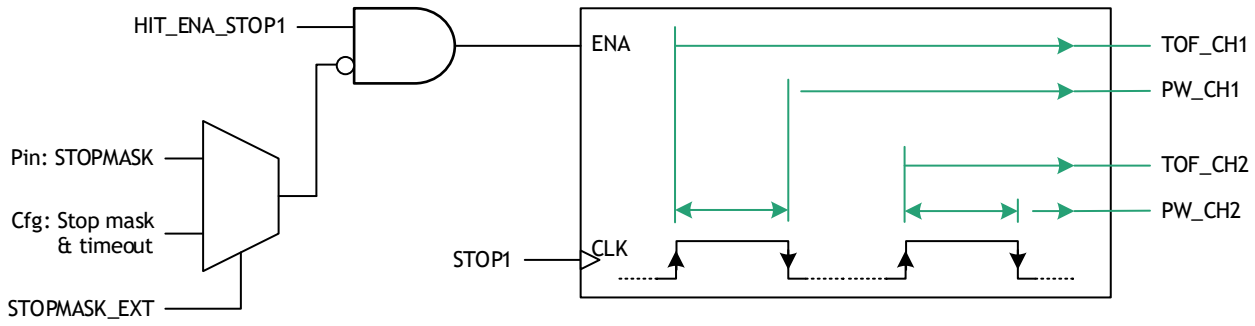


Figure 7: Channels 1 & 2 combined

7.1.3 STOPMASK

There is a dedicated CMOS input pin for a stop mask signal. With setting stop mask pin to HIGH the measurement is suppressed on both stops channels. With setting stop mask pin to LOW the measurement is enabled on both stop channels. The STOPMASK pin an alternative for internal stop mask window configured with **STOP_MASK** and **TIMEOUT**.

Table 48: STOP MASK configuration

Register	Bit	Parameter	Descrition
0x08 **CFG8**	5	**STOP_MASK_ENA**	Enables noise mask or pin STOP_MASK for stop hits after hit on start input a configured time is wait, until the first stop hit is accepted 0: stops enabled 1: stops masked
	4	**STOP_MASK_EXT**	Selects source of noise mask 0: by noise mask delay line 1: by noise mask pin

7.1.4 REF_OSC

The oscillator provides the master clock to the digital core. A biasing resistor is used to guarantee proper biasing points at DC. If lower value is needed an external resistor can be added.

Note: the oscillator is meant to deliver full performance in the primary operating range. In the “undervoltage” condition the oscillator will be functional but there could be a degradation of the performances.

The reference clock serves as universal time base. Due to internal averaging, the phase jitter of the reference clock is non-critical. The accuracy and drift of the reference clock will not affect the proper working of LTDC-X3 itself, but it will directly affect the time measurement results as they all are calibrated against the reference clock. It is possible to connect a quartz crystal or a ceramic resonator. But certainly, the selection will directly affect the quality of the time measurement results.

When the crystal driver is disabled, an external oscillator can be used for test purposes. The external clock shall be applied to the REFOSCI pin, while REFOSCO is not connected.

Table 49: Oscillator

Register	Bit	Parameter	Descrition
0x2F **ANALOG_CFG5**	1	**OSC_ENA**	0: external clock applied 1: Oscillator enabled

7.2 Start-up Sequence

- Apply/send POR reset.
- Configure the chip, including reference oscillator enable.
- In case the trigger output is used: send tdc_cal_dly2_tri and wait for 50 ms to calibrate the delay line.
- In case the noise mask is used: send tdc_cal_dly1_stm and wait 50 ms for calibration.
- Start the measuring sequence by sending tdc_init.
- The chip waits for synchronization of REFCLK
- The chip enables the TDC and waits 19 periods of the reference clock
- The chip enables the START channel

7.3 Time Measurements and Results

The reference clock is the framework for all time measurements. Internally, all events (START, rising and falling edges at STOPX) are measured against the reference clock. The TDC automatically calculates the time differences between STOP and START and calibrates those against the reference clock. Optionally, the pulse width can be calculated. The user reads the calibrated 24-bit results as TOF_CHx and PW_CHx, where PW could be the pulse width or the time for the falling edge.

- t_{START} is the internal TDC measurement of a start pulse
- t_{STOP} is the internal TDC measurement of a stop pulse
- t_{REF} is the internal TDC measurement of the reference clock period to calibrate the results
- TOF_CH1 is the time difference from START
- PW_CH1 is the pulse width of the hit or the time difference to START for the falling edge

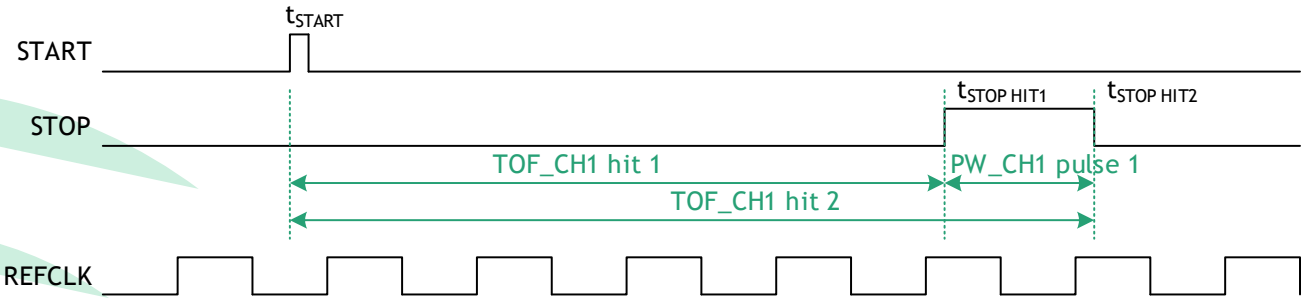


Figure 8: Time Measurement

7.3.1 Reinitialization

The LTDC-X3 needs to be re-initialized for each measurement. There are several options to do this:

- Initialization only when all data were read out of the hit buffer and the interrupt went back to high (SSN_INIT_EN = 1: EFLAG = 1, SSN=”goes back to one” = “rising edge”). This takes 5 cycles of the reference clock.
- Automatically on a rising edge on SSN pin, even if valid data are still in the buffer . This takes 5 cycles of the reference clock.
- Positive pulse on pin REINIT. This can be done any time and takes 5 cycles of the reference clock.
- Via SPI opcode TDC-REINIT, independent from hit buffer fill state, possible even during an active measuring sequence. This can be sent an time and takes 5 cycles of the reference clock.

7.3.2 Stop Mask

Besides the pin STOPMASK there is a digital delay line that can be used to mask stops internally. This stop masks begins with a valid START and releases the STOP input after the configured time interval. This helps to suppress noise or short range signals. The range can be configured from 0 to 255 ns in steps of 1ns.

During start-up delay line has to calibrate by sending opcode tdc_cal_dly1_stm. Calibration should be repeated from time to time, especially if temperature varies. The following parameters are important for the configuration:

Table 50: Stop mask

Register	Bit	Parameter	Descrition
0x03 **CFG3** 0x04 **CFG4**	7:0 11:8	**DELSTM_DLY**	Delay for STOP mask. Counted in **DELSTM_LSB**, 0 to 4095
0x08 **CFG8**	3:2	**DELSTM_LSB**	LSB as fraction of reference clock period 0: 1/1024 * T_{ref} (e.g.100 ps @ 10 MHz) 1: 2/1024 * T_{ref} 2: 5/1204 * T_{ref} 3: 10/1024 * T_{ref} (e.g.1 ns @ 10 MHz)
	5	**STOP_MASK_ENA**	1:= enable the STOP mask
	4	**STOP_MASK_EXT**	0: source is an internal delay line 1: mask via STOPMASK pin.

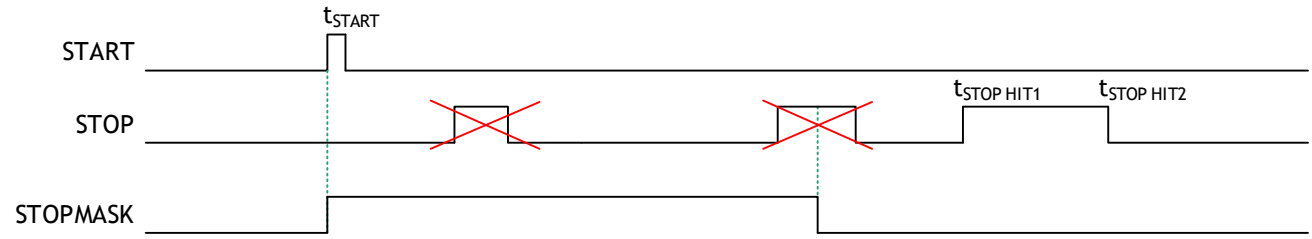


Figure 9: Stop Masking

7.3.3 Timeout

The timeout defines the measurement range by setting a time limit before which the set number of hits should have been arrived. If not enough hits are there the timeout sets the interrupt. Typically the limit is 2 µs for 300m range. It is set in parameter **TIMEOUT**, register 2.

Table 51: Timeout

Register	Bit	Parameter	Description
0x02 **CFG2**	7:0	**TIMEOUT**	8-BitTimeout counter, synchronized to start. 0: timeout generation off 1: One period of the reference clock … 255: maximum 255 periods of the refrence clock

The start of timeout counter is synchronized to start pulse. This means that there is an uncertainty in the timeout window of one period of the reference clock.

7.3.4 Interrupt

Each TDC measurement is stored in the internal hit buffer. The buffer size is configurable. A low level at the interrupt pin indicates to the external microcontroller that the measurement is done and valid data are available. This occurs either if the last accepted stop hit has filled the configured buffer space or when a timeout has occurred.

The interrupt is kept low until all data in the data buffer is read out. It is indicated via the interrupt pin.

7.3.5 High Resolution Mode

In high resolution mode the stop events are internally delayed and measured several times. The standard deviation is reduced by this method, but as a trade of the pulse-pair resolution is worse.

Table 52: High resolution mode

Register	Bit	Parameter	Description
0x00 **CFG0**	5:4	**HIGHRES**	Multiply the STOP hits internally for higher resolution 0: off standard resolution with minimum pulse-to-pulse spacing. 1: a stop event is measured twice 2: a stop event is measured four times

7.3.6 TDC Result

The output result TSTOP is the ratio of the internal measured times of t_{STOP} over t_{REF} scaled by the configured REFCLKDIV. These measurements and calculations are done automatically inside of the chip. The read-out result is in multiple of the configured LSB. The LSB is given by the ratio of the refence clock period over the configured REFCLKDIV. The LSB at the output interface should be chosen lower than the single shot resolution of the LTDC-X3. Suitable values are e.g., 1 ps, 5 ps or 10 ps.

$$t_{STOP} = TOF_CHx \times LSB = TOF_CHx \times \frac{T_{refclk}[ps]}{REFCLKDIV}$$

$$\text{or} \qquad TOF_CHx = \frac{t_{STOP}}{T_{refclk}} \times REFCLKDIV$$

Figure: Time Calculation

7.3.7 Hit Buffer

Time measurement data are stored in two hit buffers, each with maximum 16 events. Per channel this means 8 time data and 8 pulse width data can be stored. The hit buffer size can be configured from 1 to 8. When the two channels are combined the buffer size reaches from 2 to 16.

Table 53: Hit buffer configuration

Register	Bit	Parameter	Descrition
0x01 **CFG1**	5:3	**HITBUFSIZE2**	Number of hits allowed/expected in hit buffer 2
	2:0	**HITBUFSIZE1**	Number of hits allowed/expected in hit buffer 1

The fill levels of the hit buffers are indicated in the status registers **TDC_STSA_REG1** to …**REG3**.

- **EF_STA_R** Empty flag for START channel with rising edge
- **EF_STOx_y** Empty flag for channel x with slope y
- **FF_STOx_y** Full flag for channel x with slope y
- **FCNT_STOx_y** Hit counter for channel x with slope y

The content of the hit buffers is read from registers 0x15 to 0x20 which hold the values for

- **TOF_CH1** Time-of-flight channel 1 rising edge
- **PW_CH1** Pulse width channel 1 or second ToF channel 1
- **TOF_CH2** Time-of-flight channel 2 rising edge
- **PW_CH2** Pulse width channel 2 or second ToF channel 2

Those read registers are refilled from the hit buffer when a TOF & PW combination was read (FIFO principle). Reading can be done in single access mode or incremental mode. For a faster transfer it is further possible discard the LSB of TOF and PW data or to discard PW data at all. For details please see section 7.5.

7.4 Trigger Generation Module

The Start Generation Module is an independent module that provides a high configurable start signal which can be used to start the Lidar measurement. Frequency and pulse width are configurable. The signal is available on the TRIGGER pin.

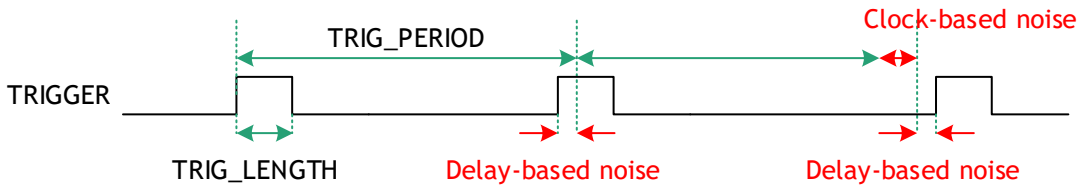


Figure 10: Trigger

The base frequency is given by the reference clock (typical 10MHz, maximum 20MHz). The period has to cover at least the maximum time measuring range of 4us.

A systematic sequence-delay ("Jitter-Sequence") can be applied to distinguish between different LIDAR systems. Two methods can be used:

- Clock-based: noise is added to the trigger period before every shot and is set in steps of the reference clock period. The main idea is to decorrelate stops received from light sources transmitting on the same frequency. It is also a fallback option to delay-based noise.
- Delay-based: noise is added to the trigger which is based on an internal delay line. The delay can be set in configurable steps of nanoseconds on top of the trigger period and the digital noise. During start-up the delay line has to be calibrated by sending opcode tdc_cal_dly2_tri. The calibration should be repeated from time to time, especially if temperature varies.

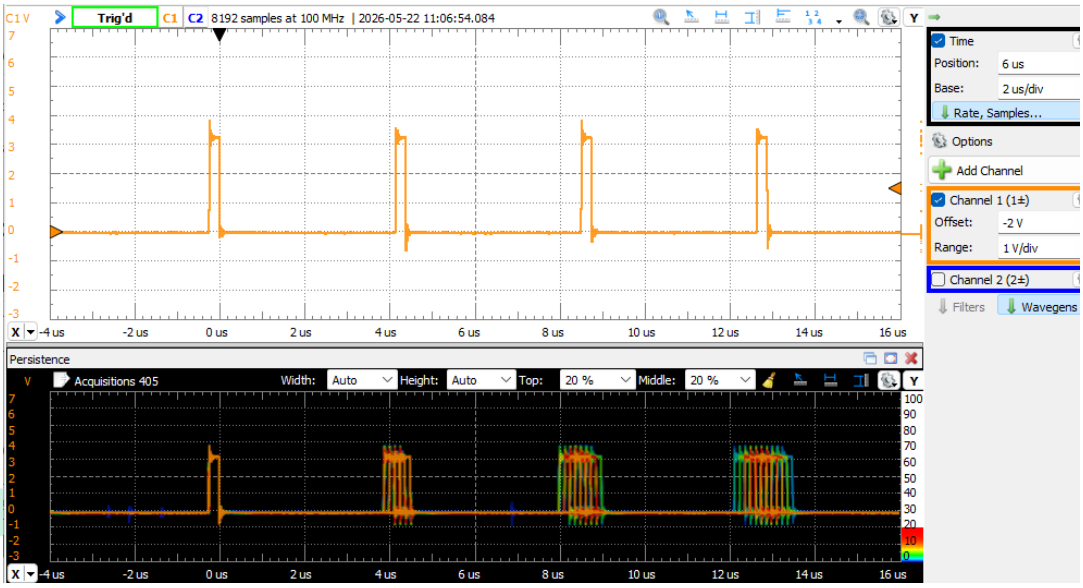


Figure 11: Clock-based noise

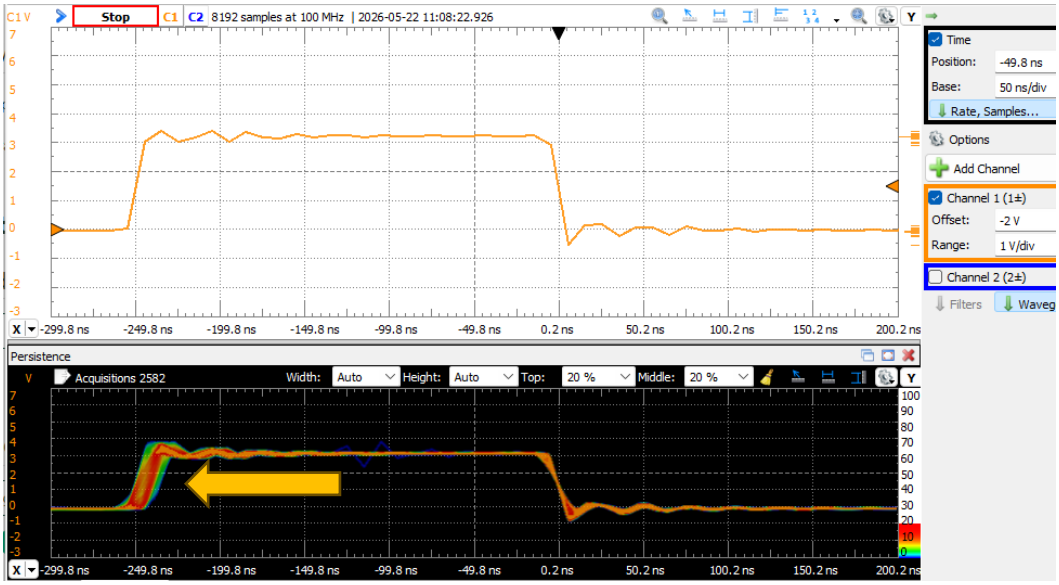


Figure 12: Delay-based noise

Table 54: Trigger configuration

Register	Bit	Parameter	Description
0x3B	6:5	**TRIG_NOISE**	Defines the amplitude of trigger noise 0 to 3 periods of the reference clock
	4:1	**TRIG_LENGTH**	Defines seed of pseudo random sequence 0 to 255
	0	**TRIG_ON**	Turns on the trigger
0x3C	7:0	**TRIG_PERIOD**	Defines the amplitude of trigger noise 0 to 7 periods of the reference clock
0x08	1:0	**DELTRIG_LSB**	Length of LSB of trigger delay as a fraction of the reference clock period: 0: 1/1024 * T_{ref} (e.g.97 ps @ 10 MHz) 1: 2/1024 * T_{ref} 2: 5/1204 * T_{ref} 3: 10/1024 * T_{ref} (e.g.0.976 ns @ 10 MHz)
0x09	7:0	**TRIG_MAX_DEL**	Maximum delay count for tigger output in **DELTRIG_LSB**

7.5 QSPI Communication Interface

The QUAD-SPI interface is implemented to

- Reset the chip to power on state
- Write configuration registers
- Verify configuration or status registers
- Initialize and restart measurements
- Byte-wise readout of results from the read registers by standard SPI and quad SPI

The serial interface is compatible with the 4-wire SPI standard in Motorola specification:

- Clock Phase Bit = 0 Clock Polarity Bit = 0
- Clock Phase Bit = 1 Clock Polarity Bit = 1

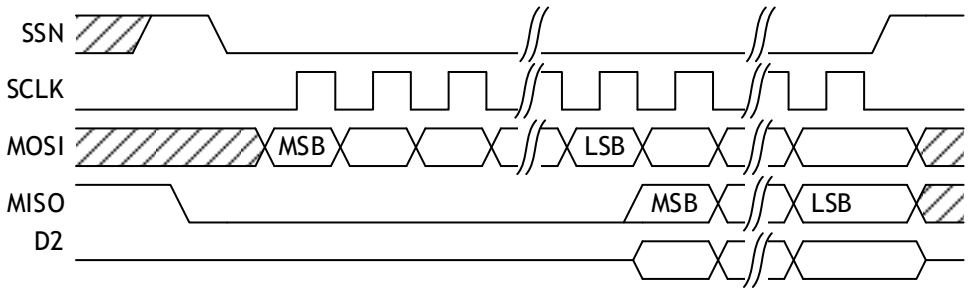


Figure 13: QSPI signals

Table 55: Opcode overview

Opcode	Hex	Description
power_up	0x30	Power on reset and stop measurement
init	0x18	Initialize chip and start measurement
tdc_reinit	0x19	Re-initialize TDC and hit buffers, TDC waits for next hits afterwards
tdc_stop	0x20	Stops TDC measurement, helps to minimize configuration
tdc_cal_dly1_stm	0x21	Calibration of delay line for stop mask
tdc_cal_dly2_tri	0x22	Calibration of delay line for trigger
write_config_std	0x80	Write Configuration register
read_short_sdr	0x60	Read opcode by short addressing in standard 4 wire mode
read_24bit_sdr	0x61	Read opcode by 24 bit addressing in standard 4 wire mode
read_short_ddr	0x62	Read opcode by short addressing in double data rate mode
read_24bit_ddr	0x63	Read opcode by 24 bit addressing in double data rate mode
quad_read_short_sdr	0x6B	Read opcode by quad SPI by 8 bit address in SDR mode
quad_read_24bit_sdr	0x6C	Read opcode by quad SPI by 24 bit address in SDR mode
quad_read_short_ddr	0x6D	Read opcode by quad SPI by 8 bit address in DDR mode
quad_read_24bit_ddr	0x6E	Read opcode by quad SPI by 24 bit address in DDR mode
dual_read_short	0x6F	Read opcode by quad SPI by 8 bit address in SDR mode
dual_read_24bit_sdr	0x70	Dual Read opcode by dual SPI by 24 bit address in SDR mode
dual_read_short_ddr	0x71	Read opcode by dual read SPI by 8 bit address in DDR mode

dual _read_24bit_ddr	0x72	Read opcode by dual read SPI by 8 bit address in DDR mode

7.5.1 Power-on Reset

After stabilization of all VDD33 and VDD18 the device expects the opcode power_up = 0x30 to be sent via the SPI interface for power on reset. After the last bit of the opcode is sent the reset remains active until SSN goes high (t_{por}).

After the reset the measurement stops and the configuration registers are set to internal defaults of the chip.

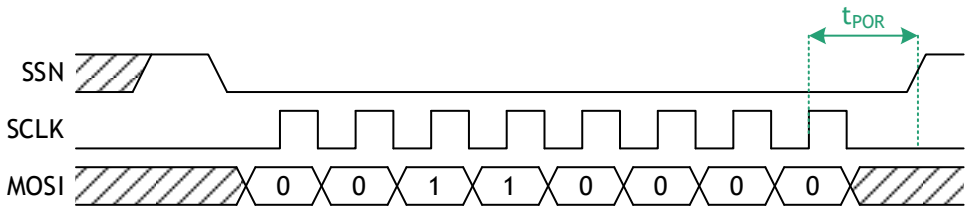


Figure 14: Opcode power_up

7.5.2 Initialization Reset (soft reset)

After the configuration, the initialization opcode init (0x18) resets again the chip to power-on state, but preserves the configuration and starts the measurement. The initialization reset can be send any time while the reference clock is applied or a measurement is running. It takes 19 periods of the reference clock before the stop channels are opened internally.

7.5.3 TDC Re-initialization (hit buffer reset)

After the configuration or measurement, the TDC re-initialization opcode tdc_reinit (0x19) re-initializes hit buffers. The TDC internal counters are not affected. After this command the TDC is ready to wait for the next hits. It takes 5 periods of the reference clock before the stop channels are opened internally.

7.5.4 TDC Stop

The opcode tdc_stop (0x20) stops an ongoing measurement. The configuration registers can be updated partially or totally after receiving of this command.

Afterwards, the TDC is restarted by opcodes tdc_reinit (0x19) or init (0x18).

7.5.5 Write / Incremental Write

Write access is permitted to the configuration registers exclusively. The access starts with the falling edge of SSN and sending the opcode write_config_std (0x80). The target register address just follows the opcode, followed then by the data. Incremental write access to the successive registers is possible by sending directly the next data bytes while SSN stays LOW. A complete configuration starts normally at register 0, followed by all register data bytes.

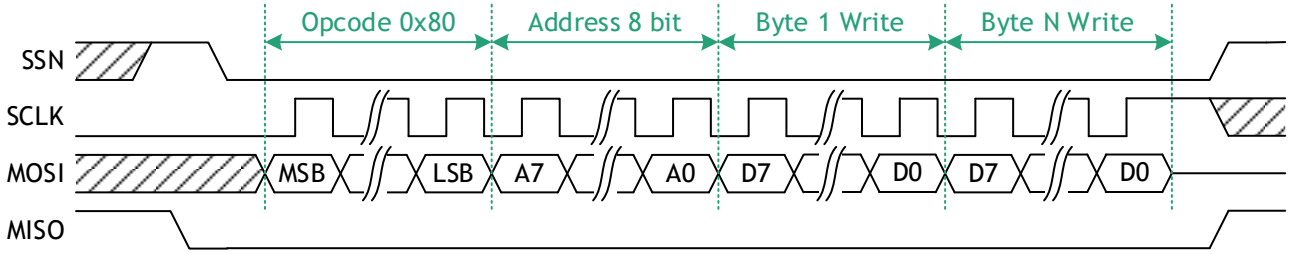


Figure 15: Opcode power_up

7.5.6 Read / Incremental Read in STD & DDR

The read access to the registers starts with the falling edge of SSN followed by sending the opcodes

- read_short_sdr (0x60) for an 8-bit address, reading in standard mode, or
- read_24bit_sdr (0x61) for a 24-bit address, reading in standard mode, or
- read_short_ddr (0x62) for an 8-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock, or
- read_24bit_ddr (0x63) for an 24-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock.

The target register address just follows the opcode. Afterwards, the data are clocked out at the MISO line. Incremental read access to the subsequent registers is possible by continuously sending clock cycles. Each register is suitable as start address for an incremental access.

Note: DDR mode is fully usable with 20 MHz bus clock, but is limited in the usable combinations when having 50 MHz bus clock. With 50 MHz the following combinations are possible:

- Quad DDR for dual channel (6 bytes)
- Dual DDR 6,4-bytes transfer mode
- Single DDR

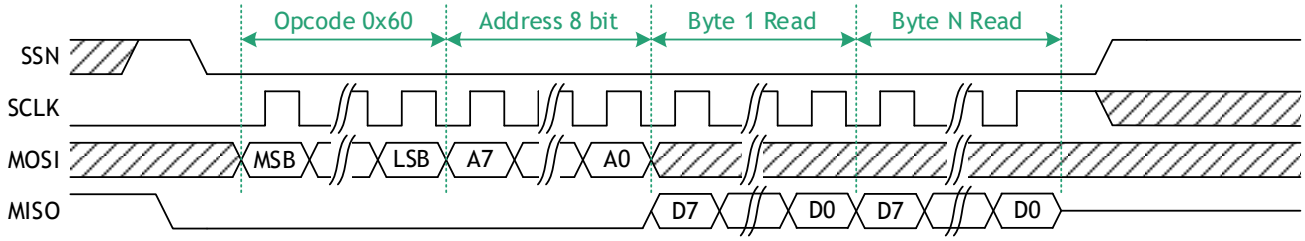


Figure 16: Read results/read incremental results at short address in STD mode

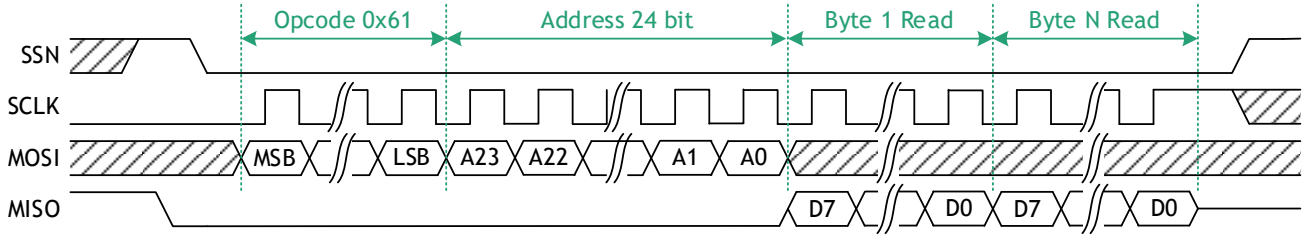


Figure 17: Read results/read incremental results at 24 bits address in STD mode

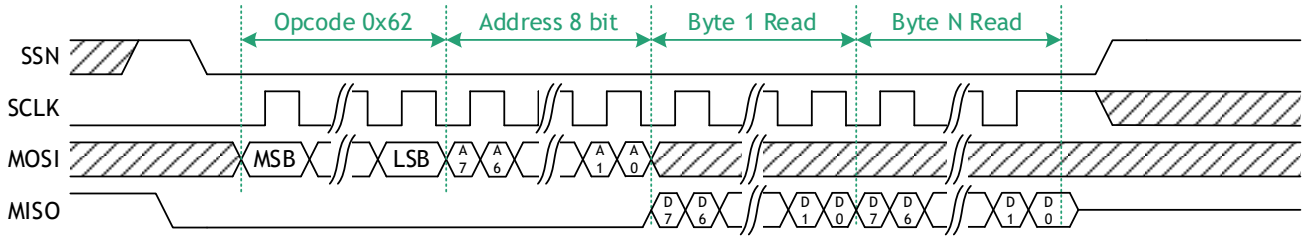


Figure 18: Read results/read incremental results at short address in DDR mode

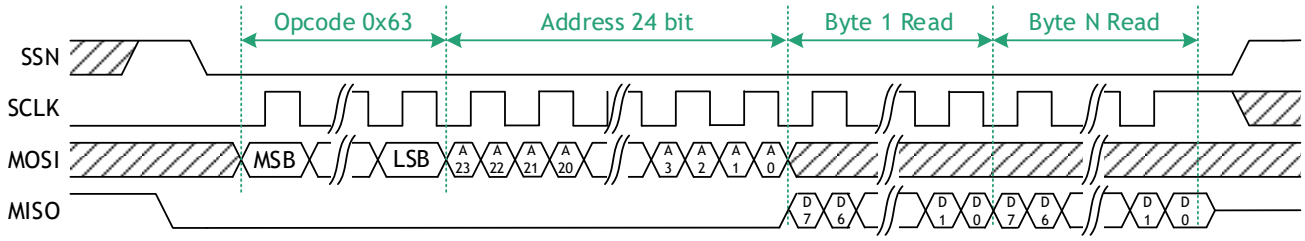


Figure 19: Read results/read incremental results at 24 bits address in DDR mode

7.5.7 Quad Read

The QSPI interface allows a quad mode in which address and data are transmitted via 4 data lines. This needs to be enabled by setting parameter EN_QUAD = 1 in register COM_SET (0x13). Otherwise, quad-mode-related opcodes are skipped.

The quad read access to the registers starts with setting SSN LOW and sending one of the opcodes

- quad_read_short_sdr (0x6B) for an 8-bit address, reading in standard mode, or
- quad_read_24bit_sdr (0x6C) for a 24-bit address, reading in standard mode, or
- quad_read_short_ddr (0x6D) for an 8-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock, or

- quad_read_24bit_ddr (0x6E) for an 24-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock.

The target register address just follows the opcode. Afterwards, the data are at the lines D0_MOSI, D1_MISO , D2 and D3. Incremental read access to the subsequent registers is possible by continuously sending clock cycles. Each register is suitable as start address for an incremental access.

Address bits A23 to A7 are discarded during the read decoding when short addressing is selected (8 bit address instead of 24 bit address).

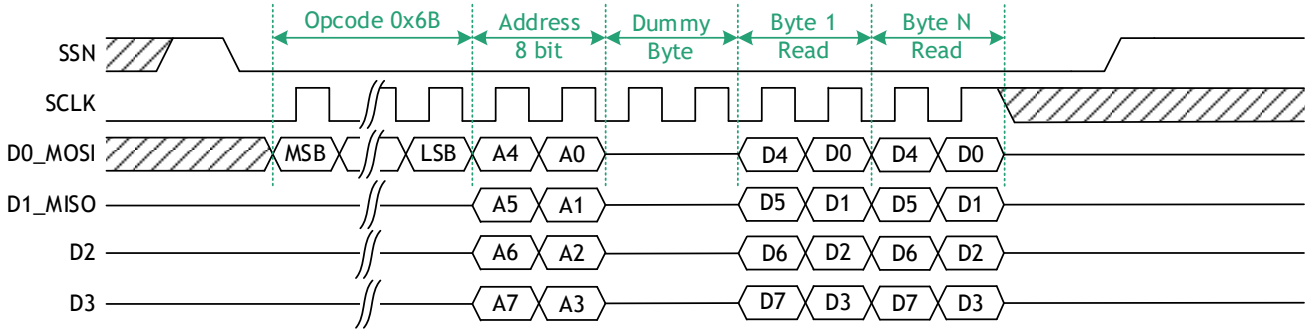


Figure 20: Quad read short address in SDR mode

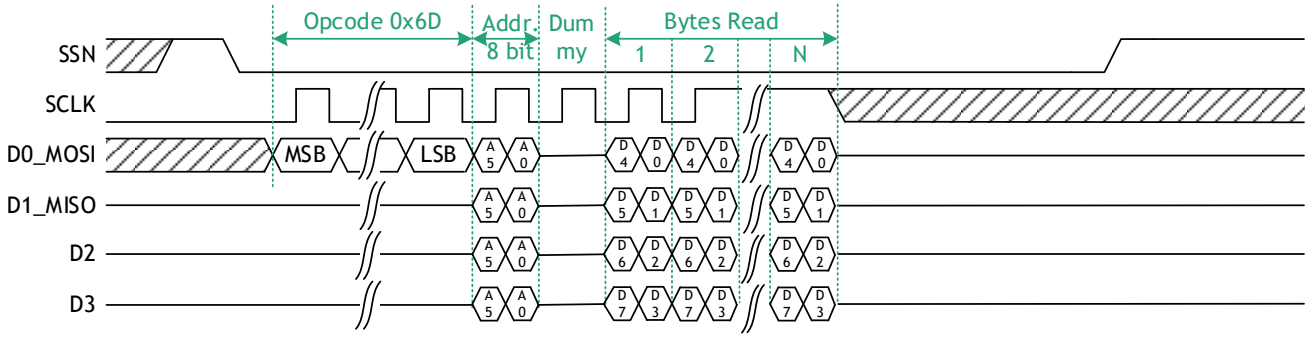


Figure 21: Quad read short address in DDR mode

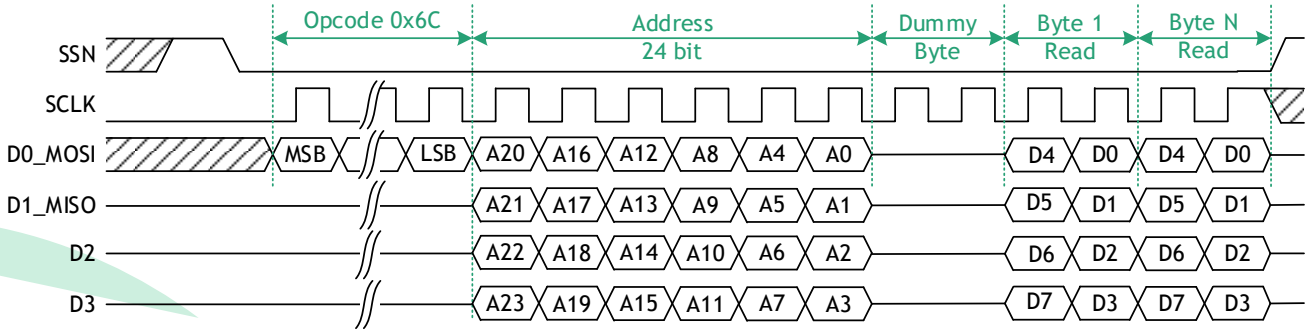


Figure 22: Quad read 24 bit address in SDR mode

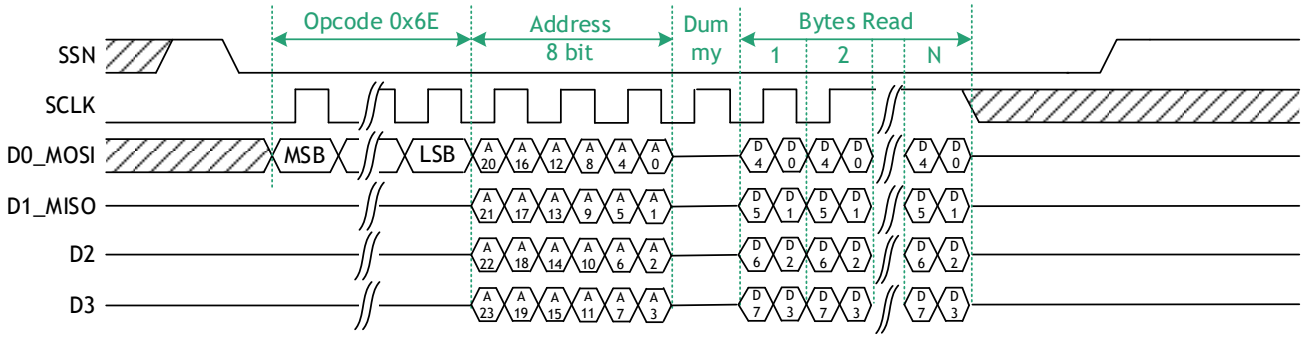


Figure 23: Quad read 24 bit address in DDR mode

7.5.8 Dual Read

The QSPI interface allows a dual mode in which address and data are transmitted via 2 data lines. This needs to be enabled by setting parameter EN_DUAL = 1 in register COM_SET (0x13). Otherwise, quad-mode-related opcodes are skipped.

The quad read access to the registers starts with setting SSN LOW and sending one of the opcodes

- dual_read_short_sdr (0x6F) for an 8-bit address, reading in standard mode, or
- dual_read_24bit_sdr (0x70) for a 24-bit address, reading in standard mode, or
- dual_read_short_ddr (0x71) for an 8-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock, or
- dual_read_24bit_ddr (0x72) for an 24-bit address, reading in double data read mode, reading with both, rising and falling edge of the clock.

The target register address just follows the opcode. Afterwards, the data are at the lines D0_MOSI, and D1_MISO. Incremental read access to the subsequent registers is possible by continuously sending clock cycles. Each register is suitable as start address for an incremental access.

Address bits A23 to A7 is discarded during the read decoding when short addressing is selected (8 bit address instead of 24 bit address).

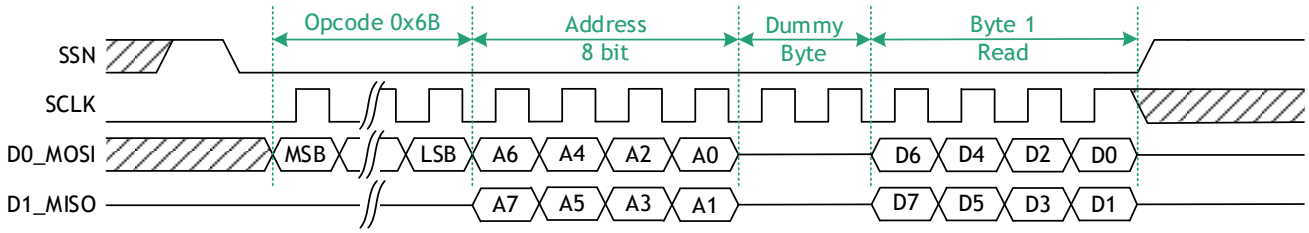


Figure 24: Dual read short address in SDR mode

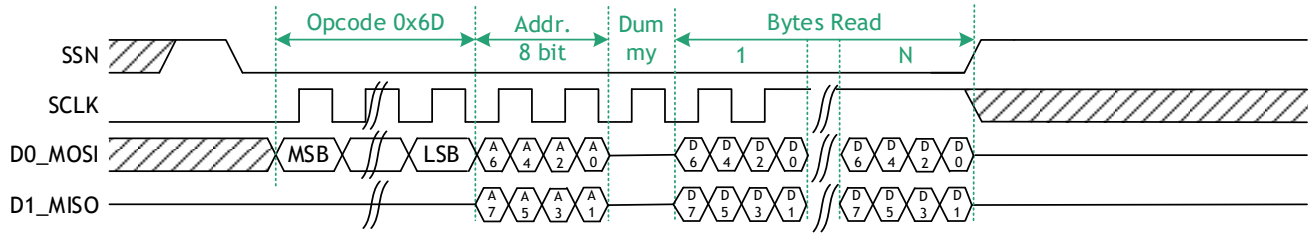


Figure 25: Dual read short address in DDR mode

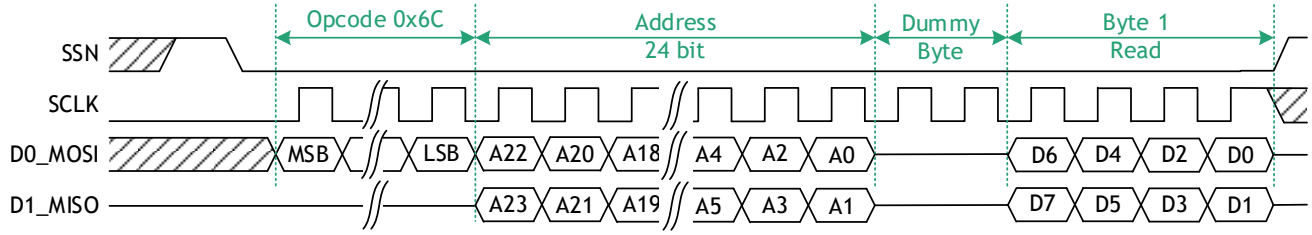


Figure 26: Dual read 24-bit address in SDR mode

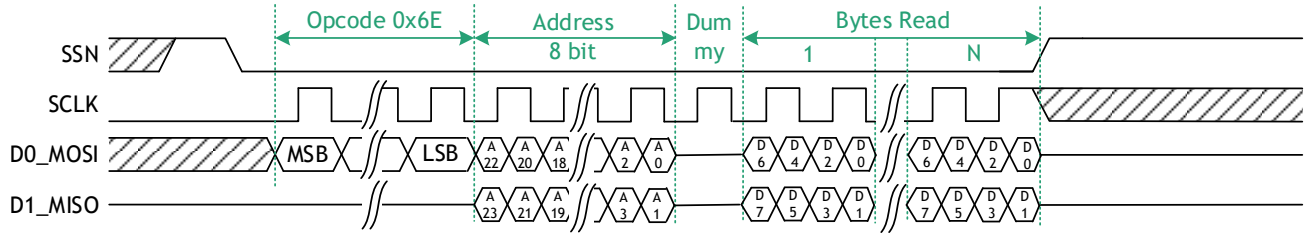


Figure 27: Dual read 24-bit address in DDR mode

7.5.9 QSPI Transfer & Measure Rates

The QSPI data rate depends on the SPI mode and read mode as well as the number of data read. The total measure rate is finally defined by the whole measure sequence and depends on multiple variables like

- Time-of-flight (maximum distance), Number of receive hits, Transfer mode (Read pulse width or not, read 2 or 3 bytes), Read status or not

The following table shows some possible scenarios. The maximum measure rate may vary from 100 ksps to 500 ksps.

Table 56: QSPI transfer rates SDR, 5 MHz reference, 100m distance

S/D	#Dx	Init ns	Dist. m	ToF ns	INTN ns	fspi MHz	Transfer mode	Hits on Ch 1	Hits on Ch 2	Status	Measure rate ksps
SDR	Single	1000	100	660	100	50	0 (6 bytes)	1	0	0	329
							1 (4 bytes)				368
							2 (3 bytes)				391
							0		1		250
							1				298
							2				329
	Quad						0		0		455
							1				472
							2				481
	Single						0	4	4	1	95
							1				125
							2				149
	Quad						0				219
							1				255
							2				278

Table 57: QSPI transfer rates SDR, 10 MHz reference, 10m distance

S/D	#Dx	Init ns	Dist. m	ToF ns	INTN ns	fspi MHz	Transfer mode	Hits on Ch 1	Hits on Ch 2	Status	Measure rate ksps
SDR	Single	400	10	66	100	50	1 (4 bytes)	1	0	0	655
										1	499
	Quad									0	1080
										1	778

Table 58: QSPI transfer rates DDR, 5 MHz reference, 100m distance

S/D	#Dx	Init ns	Dist. m	ToF ns	INTN ns	fspi MHz	Transfer mode	Hits on Ch 1	Hits on Ch 2	Status	Measure rate ksps
DDR	Single	1000	100	660	100	50	0 (6 bytes)	1	1	1	291
								4	4		158
							2 (3 bytes)				227
	Quad						1 (4 bytes)	1	1	0	495
										1	410
								4	4		410

7.5.10 QSPI Configuration

The following parameters are relevant for the configuration of the quad SPI interface.

Table 59: QSPI configuration

Register	Bit	Parameter	Description
0x11 **WRN_LOCK**	0	**WRN_LOCK**	Write no lock register
0x13 **COM_SET**	0	**DUMMY_CYCLE**	Sets the number of dummy cycles present in the Dual SPI and Quad SPI communication. Values can range from 0 to up to 15 clock cycles.
	3:2	**TR_MODE**	Transfer mode for reading from hit buffer: 0: Default mode. The slave reads three bytes of TOF and three bytes of PWSTOP 1:In this mode, the least significant bytes of TOF and PWSTOP are discarded, this leads to an increase in transmission speed at the expense of measurement accuracy. 2: In this mode, only the TOF is read and the PWSTOP is discarded. It is the fastest reading mode.
	1	**EN_DUAL**	Enables dual mode for the QSPI interface
	0	**EN_QUAD**	Enables quad mode for the QSPI interface
0x14 **CH_CFG**	6:3	**BUFF_SIZE**	TDC FIFO buffer size, define numbers of TOF and PWSTOP samples transmitted during the access: Samples = buff_size +1 the default means no limitation
	2:1	**CH_CFG**	Channel read out configuration 0: OFF 1: read channel 1 only

			2: read channel 2 only 3: read channel 1 & 2 alternatingly
	0	**ACCMODE**	Defines the access mode. 0: Single access.Each read is for one TOF and PWSTOP only. 1: Incremental access. In this mode, the QSPI slave refreshes the TDC data every time it has completed the reading of the previous one.

7.6 QSPI Read Access during TDC Measurement

7.6.1 Read Sequence with tr_mode[1:0] = 0x0

In this mode the user reads 3 bytes time-of-flight and 3 bytes pulse width per hit.

1) Single event access
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.
Note: Access order to 0x15 and 0x1b might be mixed on channel 1 and channel2.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR +3Bytes +SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR +3Bytes)
- Read Width of pulse#1 of STOP-Channel1 (+3Bytes +SSN=1)
- Read TOF of pulse#2 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR +3Bytes)
- Read Width of pulse#2 of STOP-Channel1 (+3Bytes +SSN=1)
- Read TOF of pulse#1 of STOP-Channel2 on 0x1b (SSN=0 +OPCODE+ADDR +3Bytes)
- Read Width of pulse#1 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TOF of pulse#2 of STOP-Channel2 on 0x1b (SSN=0 +OPCODE+ADDR +3Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

2) Incremental DMA access of Stop-CH1 and Ch2
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF
Note: In this example, HIT_BUFFER_SIZE is configured to 3, further readings are marked with 0xFFFFFF

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR +3Bytes+SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR +3Bytes)
- Read Width of pulse#1 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#1 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#1 of STOP-Channel2 (+3Bytes)
- Read TOF of pulse#2 of STOP-Channel1 (+3Bytes)
- Read Width of pulse#2 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#2 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+3Bytes)
- Read TOF of pulse#3 of STOP-Channel1 (+3Bytes)
- Read Width of pulse#3 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#3 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#3 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

3) Incremental DMA access with combined stop-channels 1&2 with a single access
Reason: Stops at pin STOP1 are send alternating to stop-channel1 and stop-channel2 to get higher pulse-pair resolution
Note: In this example, HIT_BUFFER_SIZE is configured to 2.
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.
Note: To speed up read-out it shall be possible to omit reading of pulse width.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR+3Bytes+SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+3Bytes)
- Read Width of pulse#1 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#2 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+3Bytes)
- Read TOF of pulse#3 of STOP-Channel1 (+3Bytes)
- Read Width of pulse#3 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#4 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#4 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

7.6.2 Read Sequence with tr_mode[1:0] = 0x1

Read 2 bytes of TOF and pulse width only. Least significant bytes will be ignored.

1. Single event access
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.
Access order to 0x15 and 0x1b might mixed on channel 1 and channel2.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR+3Bytes+SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+2Bytes+SSN=1)
- Read TOF of pulse#2 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+2Bytes+SSN=1)
- Read TOF of pulse#1 of STOP-Channel2 on 0x1b (SSN=0 +OPCODE+ADDR+2Bytes+SSN=1)
- Read TOF of pulse#2 of STOP-Channel2 on 0x1b (SSN=0 +OPCODE+ADDR+2Bytes+SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

2. Incremental DMA access of Stop-CH1 and Ch2 with separated SPI commands
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.
Note: In this example, HIT_BUFFER_SIZE is configured to 2.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR+3Bytes +SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+2Bytes)
- Read TOF of pulse#1 of STOP-Channel2 (+2Byte)
- Read TOF of pulse#2 of STOP-Channel1 (+2Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+2Bytes +SSN=1)

- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

3. Incremental DMA access with combined stop-channels 1&2 with a single access

Reason: Stops at pin STOP1 are send alternating to stop-channel1 and stop-channel2 to get higher pulse resolution

Note: In this example, HIT_BUFFER_SIZE is configured to 2.

Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR +3Bytes +SSN=1)
- Read TOF of pulse#1 on STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR +2Bytes)
- Read TOF of pulse#2 on STOP-Channel2 (+2Bytes)
- Read TOF of pulse#3 on STOP-Channel1 (+2Bytes)
- Read TOF of pulse#4 on STOP-Channel2 (+2Bytes)
- Read TOF of pulse#5 on STOP-Channel1 (+2Bytes)
- Read TOF of pulse#6 on STOP-Channel2 (+2Bytes)
- Read TOF of pulse#7 on STOP-Channel1 (+2Bytes)
- Read TOF of pulse#8 on STOP-Channel2 (+2Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

7.6.3 Read Sequence with tr_mode[1:0] = 0x2

Read 3 bytes of TOF, no pulse width data.

1. Single event access

Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.

Note: Access order to 0x15 and 0x1b might mixed (=two decoder).

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR +3Bytes +SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0+OPCODE+ADDR +3Bytes)
- Read Width of pulse#1 of STOP-Channel1 (+3Bytes +SSN=1)
- Read TOF of pulse#2 of STOP-Channel1 on 0x15 (SSN=0+OPCODE+ADDR+3Bytes)
- Read Width of pulse#2 of STOP-Channel1 (+3Bytes +SSN=1)
- Read TOF of pulse#1 of STOP-Channel2 on 0x1b (SSN=0+OPCODE+ADDR+3Bytes)
- Read Width of pulse#1 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TOF of pulse#2 of STOP-Channel2 on 0x1b (SSN=0+OPCODE+ADDR+3Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

2. Incremental DMA access of Stop-CH1 and Ch2 with separated SPI commands
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.
Note: In this example, HIT_BUFFER_SIZE is configured to 2.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR+3Bytes+SSN=1)
- Read TOF of pulse#1 of STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+3Bytes)
- Read Width of pulse#1 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#1 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#1 of STOP-Channel2 (+3Bytes)
- Read TOF of pulse#2 of STOP-Channel1 (+3Bytes)
- Read Width of pulse#2 of STOP-Channel1 (+3Bytes)
- Read TOF of pulse#2 of STOP-Channel2 (+3Bytes)
- Read Width of pulse#2 of STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

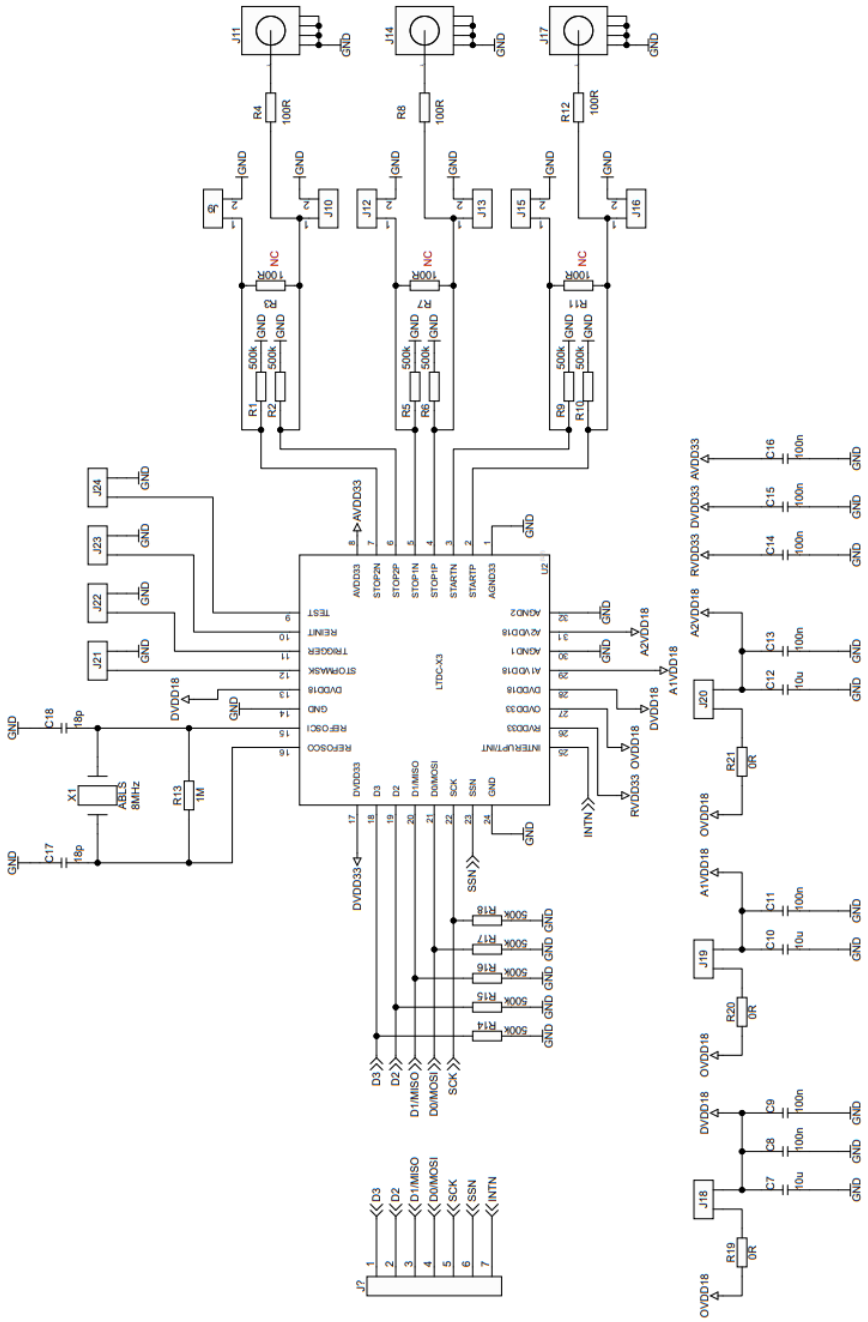
3. Incremental DMA access with combined stop-cahnne1&2 with a single access
Reason: Stops at pin STOP1 are send alternating to stop-channel1 and stop-channel2 to get higher pulse resolution
Note: In this example, HIT_BUFFER_SIZE is configured to 2.
Note: reading of status is optional, missing stop pulses are marked with 0xFFFFFF.

LOOP:

- Wait for Interrupt
- Read Status (optional) (SSN=0 +OPCODE+ADDR+3Bytes +SSN=1)
- Read TOF of pulse#1 on STOP-Channel1 on 0x15 (SSN=0 +OPCODE+ADDR+2Bytes)
- Read Width of pulse#1 on STOP-Channel1 (+3Bytes)
- Read TOF of pulse#2 on STOP-Channel2 (+3Bytes)
- Read Width of pulse#2 on STOP-Channel2 (+3Bytes)
- Read TOF of pulse#3 on STOP-Channel1 (+3Bytes)
- Read Width of pulse#3 on STOP-Channel1 (+3Bytes)
- Read TOF of pulse#4 on STOP-Channel2 (+3Bytes)
- Read Width of pulse#4 on STOP-Channel2 (+3Bytes +SSN=1)
- Read TDC_STAT_REGF on 0x22 (SSN=0 +OPCODE+ADDR +4Bytes)
- REINIT done by REINIT pin or SPI REINIT command (ssn_init_ena=0)

8 Application Information

8.1 Schematic



9 Soldering information

The ENS160 uses an open LGA package. This package can be soldered using a standard reflow process in accordance with IPC/JEDEC J-STD-020D (Figure 28).

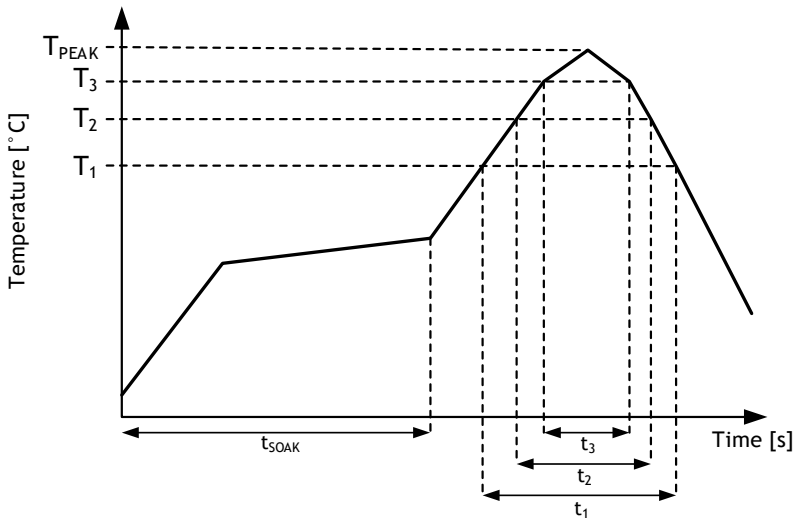


Figure 28: Solder reflow profile graph

The detailed settings for the reflow profile are shown in Table 60.

Table 60: Solder Reflow Profile

Parameter	Reference	Rate / Unit
Average temperature gradient in preheating		2.5 K/s
Soak time	t_{SOAK}	2..3 min
Soak temp range	Ts max	200°C
	Ts min	150°C
Time above 217°C (T1)	t_1	Max. 60s
Time above 230°C (T2)	t_2	Max. 50s
Time above TPEAK -10°C (T3)	t_3	Max. 10s
Peak temperature in reflow	T_{PEAK}	260°C
Temperature gradient in cooling		Max. -5K/s

It is recommended to use a no-clean solder paste. There should not be any board wash processes, to prevent cleaning agents or other liquid materials contacting the sensor area.

10 Package drawings & markings

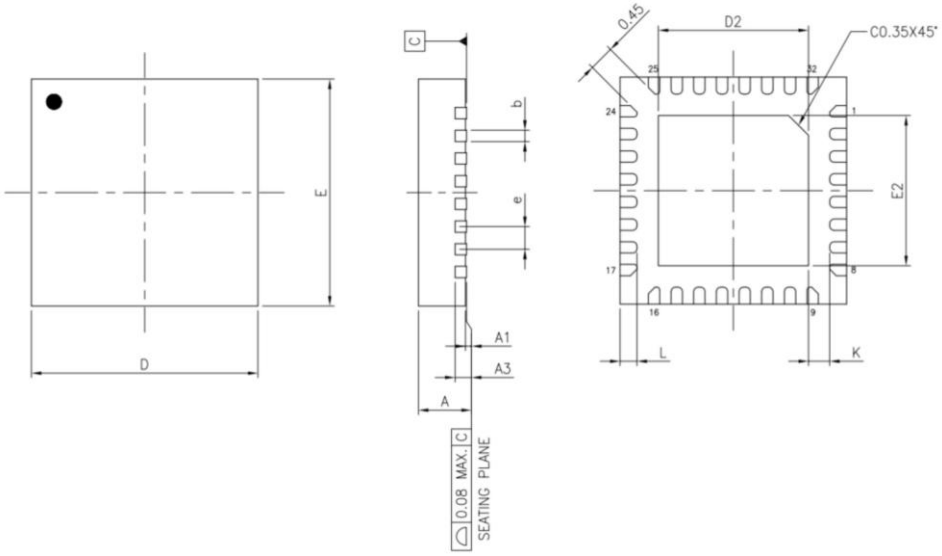


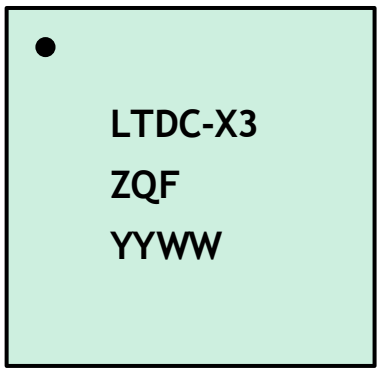
Figure 29: QFN32 package drawing

Table 61: QFN32 package dimensions

Symbol	Dimensions		
	Min	Nominal	Max
A	0.80	0.85	0.90
A1	0.00	0.02	0.05
A3		0.203 REF.	
b	0.15	0.20	0.25
D	3.90	4.00	4.10
E	3.90	4.00	4.10
D2	2.65	2.70	2.75
E2	2.65	2.70	2.75
e		0.40 BSC	
L	0.35	0.40	0.45
K	0.20	-	-

Note(s):

1. All dimensions are in millimeters.
2. PCB land pattern are shown as red dotted lines.
3. Add 0.05mm all around the nominal lead width and length for the PCB land pattern.



YY = Year, WW = Week

Figure 30: QFN32 package marking

Tape & Reel

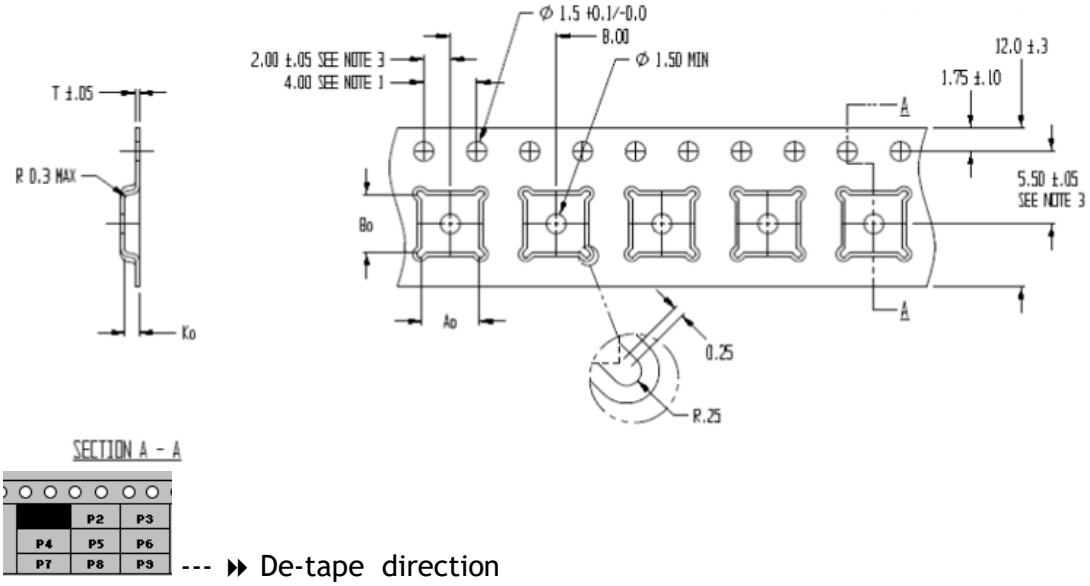


Figure 31: Tape drawing

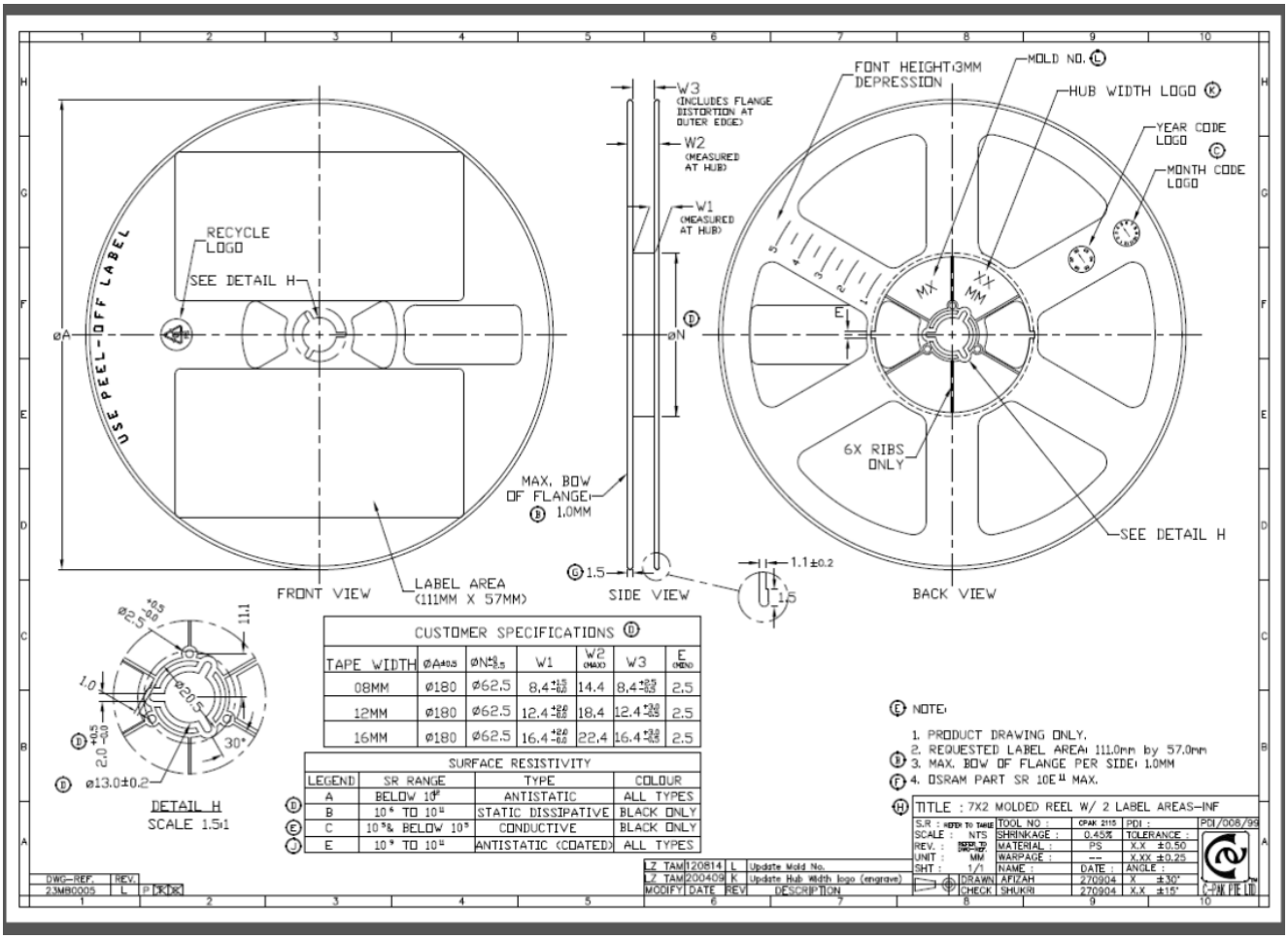


Figure 32: Reel drawing

11 Ordering information

Table 62: Ordering information

Ordering Code	Material ID	Package	Delivery Form	Delivery Quantity
LTDC-X3	503710001	QFN32	Tape & reel	1000 pcs

12 RoHS Compliance & ScioSense Green Statement

RoHS: The term RoHS compliant means that Sciosense B.V. products fully comply with current RoHS directives. Our semiconductor products do not contain any chemicals for all 6 substance categories, including the requirement that lead does not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, RoHS compliant products are suitable for use in specified lead-free processes.

ScioSense Green (RoHS compliant and no Sb/Br): ScioSense Green defines that in addition to RoHS compliance, our products are free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material).

Important Information: The information provided in this statement represents Sciosense B.V. knowledge and belief as of the date that it is provided. Sciosense B.V. bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. Sciosense B.V. has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. Sciosense B.V. and Sciosense B.V. suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

13 Copyrights & Disclaimer

Copyright **Sciosense B.V High Tech Campus 10, 5656 AE Eindhoven, The Netherlands**. Trademarks Registered. All rights reserved. The material herein may not be reproduced, adapted, merged, translated, stored, or used without the prior written consent of the copyright owner.

Devices sold by Sciosense B.V. are covered by the warranty and patent indemnification provisions appearing in its General Terms of Trade. Sciosense B.V. makes no warranty, express, statutory, implied, or by description regarding the information set forth herein. Sciosense B.V. reserves the right to change specifications and prices at any time and without notice. Therefore, prior to designing this product into a system, it is necessary to check with Sciosense B.V. for current information. This product is intended for use in commercial applications. Applications requiring extended temperature range, unusual environmental requirements, or high reliability applications, such as military, medical life-support or life-sustaining equipment are specifically not recommended without additional processing by Sciosense B.V. for each application. This product is provided by Sciosense B.V. “AS IS” and any express or implied warranties, including, but not limited to the implied warranties of merchantability and fitness for a particular purpose are disclaimed.

Sciosense B.V. shall not be liable to recipient or any third party for any damages, including but not limited to personal injury, property damage, loss of profits, loss of use, interruption of business or indirect, special, incidental or consequential damages, of any kind, in connection with or arising out of the furnishing, performance or use of the technical data herein. No obligation or liability to recipient or any third party shall arise or flow out of Sciosense B.V. rendering of technical or other services.

14 Document status

Table 63: Document status

Document Status	Product Status	Definition
Product Preview	Pre-Development	Information in this datasheet is based on product ideas in the planning phase of development. All specifications are design goals without any warranty and are subject to change without notice.
Preliminary Datasheet	Pre-Production	Information in this datasheet is based on products in the design, validation or qualification phase of development. The performance and parameters shown in this document are preliminary without any warranty and are subject to change without notice.
Datasheet	Production	Information in this datasheet is based on products in ramp-up to full production or full production which conform to specifications in accordance with the terms of ScioSense B.V. standard warranty as given in the General Terms of Trade.
Datasheet (Discontinued)	Discontinued	Information in this datasheet is based on products which conform to specifications in accordance with the terms of ScioSense B.V. standard warranty as given in the General Terms of Trade, but these products have been superseded and should not be used for new designs.

15 Revision information

Table 64: Revision history

Revision	Date	Comment	Page
2A	2025-08	CMOS pulse width External clock	8 29
3	2026-05	Section 7.4 Trigger Generation	33/34
4	2026-08	Registers: Command replaced by description Register overview RW completed DEV_STATE corrected Table 54 opcodes descriptions Center pad dimensions corrected	 12 21 36 52

Note(s) and/or Footnote(s):

1. Page and figure numbers for the previous version may differ from page and figure numbers in the current revision.
2. Correction of typographical errors is not explicitly mentioned.

Address: Sciosense B.V.
High Tech Campus 10
5656 AE Eindhoven
The Netherlands

Contact: www.sciosense.com
info@sciosense.com